勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-54151736 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

DS05-20846-4E

FLASH MEMORY

CMOS

16M (2M \times 8/1M \times 16) BIT

MBM29LV160T-80/-90/-12/MBM29LV160B-80/-90/-12

■ FEATURES

- Single 3.0 V read, program and erase Minimizes system level power requirements
- Compatible with JEDEC-standard commands Uses same software commands as E²PROMs
- Compatible with JEDEC-standard world-wide pinouts
 48-pin TSOP (I) (Package suffix: PFTN-Normal Bend Type, PFTR-Reversed Bend Type)
 46-pin SON (Package suffix: PN)
 48-pin CSOP (Package suffix: PCV)
 48-ball FBGA (Package suffix: PBT)
- Minimum 100,000 program/erase cycles
- High performance 80 ns maximum access time
- Sector erase architecture

One 8K word, two 4K words, one 16K word, and thirty-one 32K words sectors in word mode One 16K byte, two 8K bytes, one 32K byte, and thirty-one 64K bytes sectors in byte mode Any combination of sectors can be concurrently erased. Also supports full chip erase

Boot Code Sector Architecture

T = Top sector

- B = Bottom sector
- Embedded Erase[™] Algorithms Automatically pre-programs and erases the chip or any sector
- Embedded program[™] Algorithms Automatically programs and verifies data at specified address
- Data Polling and Toggle Bit feature for detection of program or erase cycle completion
- Ready/Busy output (RY/BY)
 Hardware method for detection of program or era
- Hardware method for detection of program or erase cycle completion • Automatic sleep mode

When addresses remain stable, automatically switches themselves to low power mode

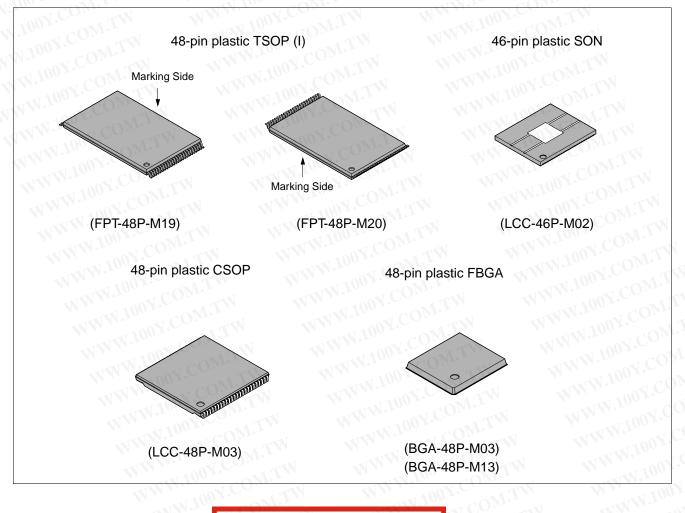
• Low Vcc write inhibit \leq 2.5 V

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- Erase Suspend/Resume
- Suspends the erase operation to allow a read data and/or program in another sector within the same device Sector protection
- Hardware method disables any combination of sectors from program or erase operations
- Sector Protection set function by Extended sector Protect command
- Temporary sector unprotection
 - Temporary sector unprotection via the RESET pin
- In accordance with CFI (Common Flash Memory Interface)

PACKAGE



GENERAL DESCRIPTION

The MBM29LV160T/B is a 16M-bit, 3.0 V-only Flash memory organized as 2M bytes of 8 bits each or 1M words of 16 bits each. The MBM29LV160T/B is offered in a 48-pin TSOP (I), 46-pin SON, 48-pin CSOP and 48-ball FBGA packages. The device is designed to be programmed in-system with the standard system $3.0 \text{ V} \text{ V}_{\text{CC}}$ supply. 12.0 V V_{PP} and 5.0 V V_{CC} are not required for write or erase operations. The device can also be reprogrammed in standard EPROM programmers.

The standard MBM29LV160T/B offers access times of 80 ns and 120 ns, allowing operation of high-speed microprocessors without wait states. To eliminate bus contention the device has separate chip enable ($\overline{\text{CE}}$), write enable ($\overline{\text{WE}}$), and output enable ($\overline{\text{OE}}$) controls.

The MBM29LV160T/B is pin and command set compatible with JEDEC standard E²PROMs. Commands are written to the command register using standard microprocessor write timings. Register contents serve as input to an internal state-machine which controls the erase and programming circuitry. Write cycles also internally latch addresses and data needed for the programming and erase operations. Reading data out of the device is similar to reading from 5.0 V and 12.0 V Flash or EPROM devices.

The MBM29LV160T/B is programmed by executing the program command sequence. This will invoke the Embedded Program Algorithm which is an internal algorithm that automatically times the program pulse widths and verifies proper cell margins. Typically, each sector can be programmed and verified in about 0.5 seconds. Erase is accomplished by executing the erase command sequence. This will invoke the Embedded Erase Algorithm which is an internal algorithm that automatically preprograms the array if it is not already programmed before executing the erase operation. During erase, the device automatically times the erase pulse widths and verifies proper cell margins.

Any individual sector is typically erased and verified in 1.0 second. (If already preprogrammed.)

The device also features a sector erase architecture. The sector mode allows each sector to be erased and reprogrammed without affecting other sectors. The MBM29LV160T/B is erased when shipped from the factory.

The device features single 3.0 V power supply operation for both read and write functions. Internally generated and regulated voltages are provided for the program and erase operations. A low V_{CC} detector automatically inhibits write operations on the loss of power. The end of program or erase is detected by Data Polling of DQ₇, by the Toggle Bit feature on DQ₆, or the RY/BY output pin. Once the end of a program or erase cycle has been comleted, the device internally resets to the read mode.

The MBM29LV160T/B also has a hardware RESET pin. When this pin is driven low, execution of any Embedded Program Algorithm or Embedded Erase Algorithm is terminated. The internal state machine is then reset to the read mode. The RESET pin may be tied to the system reset circuitry. Therefore, if a system reset occurs during the Embedded Program Algorithm or Embedded Erase Algorithm, the device is automatically reset to the read mode and will have erroneous data stored in the address locations being programmed or erased. These locations need re-writing after the Reset. Resetting the device enables the system's microprocessor to read the boot-up firmware from the Flash memory.

Fujitsu's Flash technology combines years of Flash memory manufacturing experience to produce the highest levels of quality, reliability, and cost effectiveness. The MBM29LV160T/B memory electrically erases all bits within a sector simultaneously via Fowler-Nordhiem tunneling. The bytes/words are programmed one byte/word at a time using the EPROM programming mechanism of hot electron injection.

FLEXIBLE SECTOR-ERASE ARCHITECTURE

- One 8K word, two 4K words, one 16K word, and thirty-one 32K words sectors in word mode.
- One 16K byte, two 8K bytes, one 32K byte, and thirty-one 64K bytes sectors in byte mode.
- Individual-sector, multiple-sector, or bulk-erase capability.
- Individual or multiple-sector protection is user definable.

Sector	Sector Size	(× 8) Address Range	(× 16) Address Range
SA0	64 Kbytes or 32 Kwords	00000H to 0FFFFH	00000H to 07FFFH
SA1	64 Kbytes or 32 Kwords	10000H to 1FFFFH	08000H to 0FFFFH
SA2	64 Kbytes or 32 Kwords	20000H to 2FFFFH	10000H to 17FFFH
SA3	64 Kbytes or 32 Kwords	30000H to 3FFFFH	18000H to 1FFFFH
SA4	64 Kbytes or 32 Kwords	40000H to 4FFFFH	20000H to 27FFFH
SA5	64 Kbytes or 32 Kwords	50000H to 5FFFFH	28000H to 2FFFFH
SA6	64 Kbytes or 32 Kwords	60000H to 6FFFFH	30000H to 37FFFH
SA7	64 Kbytes or 32 Kwords	70000H to 7FFFFH	38000H to 3FFFFH
SA8	64 Kbytes or 32 Kwords	80000H to 8FFFFH	40000H to 47FFFH
SA9	64 Kbytes or 32 Kwords	90000H to 9FFFFH	48000H to 4FFFFH
SA10	64 Kbytes or 32 Kwords	A0000H to AFFFFH	50000H to 57FFFH
SA11	64 Kbytes or 32 Kwords	B0000H to BFFFFH	58000H to 5FFFFH
SA12	64 Kbytes or 32 Kwords	C0000H to CFFFFH	60000H to 67FFFH
SA13	64 Kbytes or 32 Kwords	D0000H to DFFFFH	68000H to 6FFFFH
SA14	64 Kbytes or 32 Kwords	E0000H to EFFFFH	70000H to 77FFFH
SA15	64 Kbytes or 32 Kwords	F0000H to FFFFFH	78000H to 7FFFFH
SA16	64 Kbytes or 32 Kwords	100000H to 10FFFFH	80000H to 87FFFH
SA17	64 Kbytes or 32 Kwords	110000H to 11FFFFH	88000H to 8FFFFH
SA18	64 Kbytes or 32 Kwords	120000H to 12FFFFH	90000H to 97FFFH
SA19	64 Kbytes or 32 Kwords	130000H to 13FFFFH	98000H to 9FFFFH
SA20	64 Kbytes or 32 Kwords	140000H to 14FFFFH	A0000H to A7FFFH
SA21	64 Kbytes or 32 Kwords	150000H to 15FFFFH	A8000H to AFFFFH
SA22	64 Kbytes or 32 Kwords	160000H to 16FFFFH	B0000H to B7FFFH
SA23	64 Kbytes or 32 Kwords	170000H to 17FFFFH	B8000H to BFFFFH
SA24	64 Kbytes or 32 Kwords	180000H to 18FFFFH	C0000H to C7FFFH
SA25	64 Kbytes or 32 Kwords	190000H to 19FFFFH	C8000H to CFFFFH
SA26	64 Kbytes or 32 Kwords	1A0000H to 1AFFFFH	D0000H to D7FFFH
SA27	64 Kbytes or 32 Kwords	1B0000H to 1BFFFFH	D8000H to DFFFFH
SA28	64 Kbytes or 32 Kwords	1C0000H to 1CFFFFH	E0000H to E7FFFH
SA29	64 Kbytes or 32 Kwords	1D0000H to 1DFFFFH	E8000H to EFFFFH
SA30	64 Kbytes or 32 Kwords	1E0000H to 1EFFFFH	F0000H to F7FFFH
SA31	32 Kbytes or 16 Kwords	1F0000H to 1F7FFFH	F8000H to FBFFFH
SA32	8 Kbytes or 4 Kwords	1F8000H to 1F9FFFH	FC000H to FCFFFH
SA33	8 Kbytes or 4 Kwords	1FA000H to 1FBFFFH	FD000H to FDFFFH
SA34	16 Kbytes or 8 Kwords	1FC000H to 1FFFFFH	FE000H to FFFFFH

MBM29LV160T Top Boot Sector Architecture

Sector	Sector Size	(× 8) Address Range	(× 16) Address Range
SA0	16 Kbytes or 8 Kwords	00000H to 03FFFH	00000H to 01FFFH
SA1	8 Kbytes or 4 Kwords	04000H to 05FFFH	02000H to 02FFFH
SA2	8 Kbytes or 4 Kwords	06000H to 07FFFH	03000H to 03FFFH
SA3	32 Kbytes or 16 Kwords	08000H to 0FFFFH	04000H to 07FFFH
SA4	64 Kbytes or 32 Kwords	10000H to 1FFFFH	08000H to 0FFFFH
SA5	64 Kbytes or 32 Kwords	20000H to 2FFFFH	10000H to 17FFFH
SA6	64 Kbytes or 32 Kwords	30000H to 3FFFFH	18000H to 1FFFFH
SA7	64 Kbytes or 32 Kwords	40000H to 4FFFFH	20000H to 27FFFH
SA8	64 Kbytes or 32 Kwords	50000H to 5FFFFH	28000H to 2FFFFH
SA9	64 Kbytes or 32 Kwords	60000H to 6FFFFH	30000H to 37FFFH
SA10	64 Kbytes or 32 Kwords	70000H to 7FFFH	38000H to 3FFFFH
SA11	64 Kbytes or 32 Kwords	80000H to 8FFFFH	40000H to 47FFFH
SA12	64 Kbytes or 32 Kwords	90000H to 9FFFFH	48000H to 4FFFFH
SA13	64 Kbytes or 32 Kwords	A0000H to AFFFFH	50000H to 57FFFH
SA14	64 Kbytes or 32 Kwords	B0000H to BFFFFH	58000H to 5FFFFH
SA15	64 Kbytes or 32 Kwords	C0000H to CFFFFH	60000H to 67FFFH
SA16	64 Kbytes or 32 Kwords	D0000H to DFFFFH	68000H to 6FFFFH
SA17	64 Kbytes or 32 Kwords	E0000H to EFFFFH	70000H to 77FFFH
SA18	64 Kbytes or 32 Kwords	F0000H to FFFFFH	78000H to 7FFFH
SA19	64 Kbytes or 32 Kwords	100000H to 10FFFFH	80000H to 87FFFH
SA20	64 Kbytes or 32 Kwords	110000H to 11FFFFH	88000H to 8FFFFH
SA21	64 Kbytes or 32 Kwords	120000H to 12FFFFH	90000H to 97FFFH
SA22	64 Kbytes or 32 Kwords	130000H to 13FFFFH	98000H to 9FFFFH
SA23	64 Kbytes or 32 Kwords	140000H to 14FFFFH	A0000H to A7FFFH
SA24	64 Kbytes or 32 Kwords	150000H to 15FFFFH	A8000H to AFFFFH
SA25 🕥	64 Kbytes or 32 Kwords	160000H to 16FFFFH	B0000H to B7FFFH
SA26 📢	64 Kbytes or 32 Kwords	170000H to 17FFFH	B8000H to BFFFFH
SA27	64 Kbytes or 32 Kwords	180000H to 18FFFFH	C0000H to C7FFFH
SA28	64 Kbytes or 32 Kwords	190000H to 19FFFFH	C8000H to CFFFFH
SA29	64 Kbytes or 32 Kwords	1A0000H to 1AFFFFH	D0000H to D7FFFH
SA30	64 Kbytes or 32 Kwords	1B0000H to 1BFFFFH	D8000H to DFFFFH
SA31	64 Kbytes or 32 Kwords	1C0000H to 1CFFFFH	E0000H to E7FFFH
SA32	64 Kbytes or 32 Kwords	1D0000H to 1DFFFFH	E8000H to EFFFFH
SA33	64 Kbytes or 32 Kwords	1E0000H to 1EFFFFH	F0000H to F7FFFH
SA34	64 Kbytes or 32 Kwords	1F0000H to 1FFFFH	F8000H to FFFFFH

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MBM29LV160B Bottom Boot Sector Architecture 勝特力材料886-3-5753170 胜特力电子(上海) 86-21-54151736 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

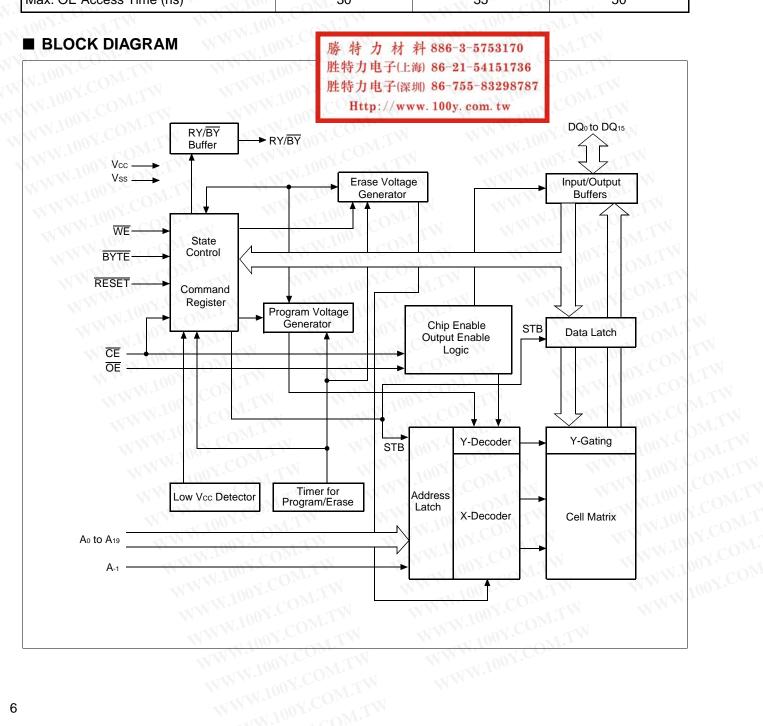
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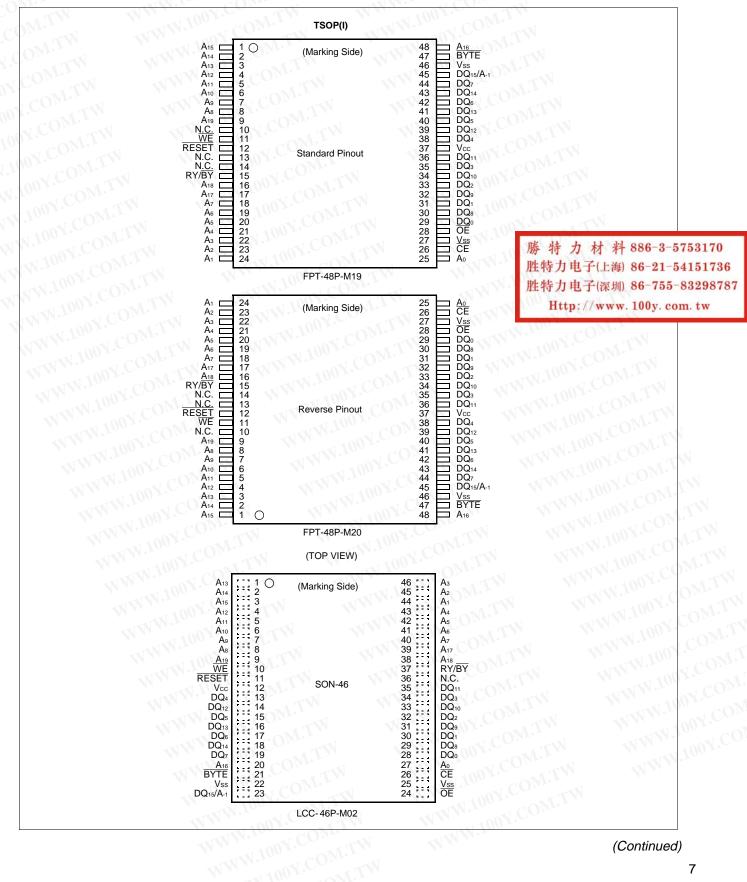
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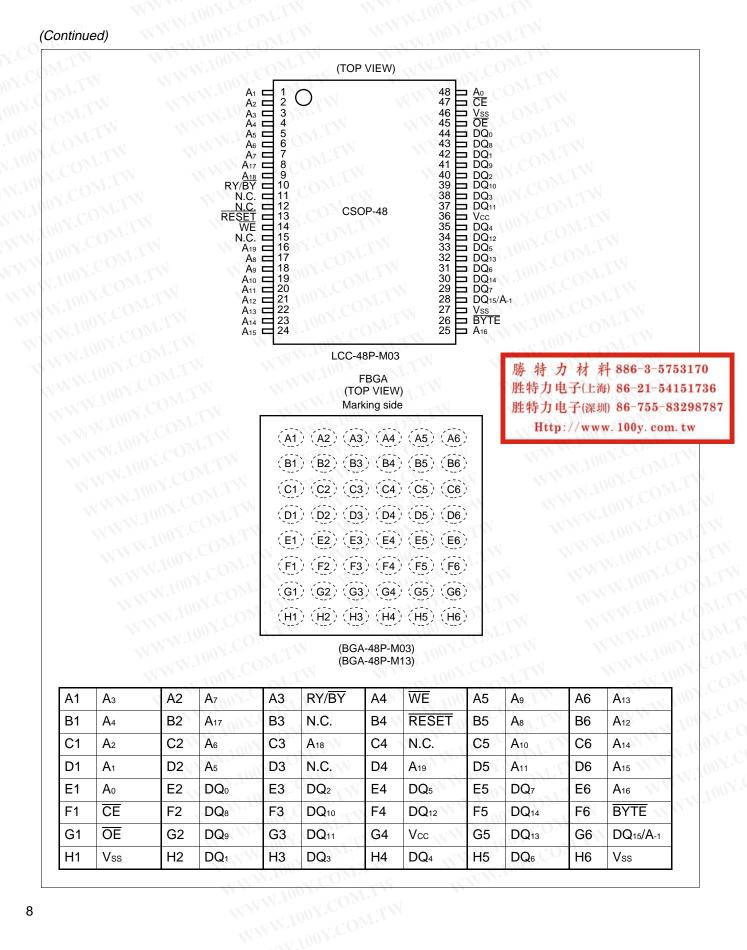
Pa	rt No.	MBM29LV160T/160B								
Ordering Part No	$V_{cc} = 3.3 V_{-0.3 V}^{+0.3 V}$	-80	N.100Y.COM.I.	—						
Ordering Part No.	$V_{cc} = 3.0 V_{-0.3 V}^{+0.6 V}$	MITH WY	-90	-12						
Max. Address Acce	ss Time (ns)	80	90	120						
Max. CE Access Tir	me (ns)	80	90	120						
Max. OE Access Ti	me (ns)	30	35	50						



CONNECTION DIAGRAMS



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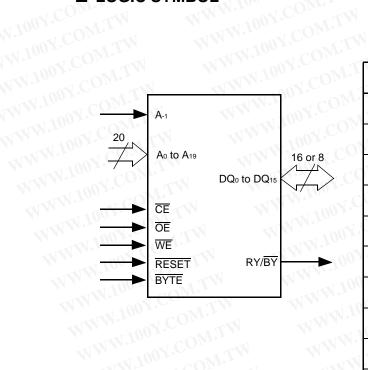


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N.100Y.COM.TW WWW.100Y.COM.TW LOGIC SYMBOL

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A-1, A0 to A19	Address Inputs
	N. LON.
DQ0 to DQ15	Data Inputs/Outputs
CE	Chip Enable
ŌĒ	Output Enable
WE	Write Enable
RY/BY	Ready/Busy Output
RESET	Hardware Reset Pin/ Temporary Sector Unprotection
BYTE	Selects 8-bit or 16-bit mode
N.C.	Pin Not Connected Internally
Vss	Device Ground
Vcc	Device Power Supply

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W.100Y.COM.TW Table 1 MBM29LV160T/B Pin Configuration

Operation	CE	OE	WE	Ao	A 1	A	A۹	DQ ₀ to DQ ₁₅	RESE
Auto-Select Manufacture Code (1)	L	L.	Н	Ľ	1001	L	VID	Code	Н
Auto-Select Device Code (1)	L	TL	Н	Н	00 <u>1,</u> 100	Ľ	Vid	Code	Н
Read (3)	L	L	Н	Ao	A ₁	A6	A ₉	Dout	Н
Standby	Н	X	Х	Х	X	Х	X	HIGH-Z	Н
Output Disable	O L	H.T	Н	Х	Х	X	X	HIGH-Z	Н
Write (Program/Erase)	005.	HI.	L	Ao	A1	A6	A9	DIN	Н
Enable Sector Protection (2), (4)	7051.	Vid	Ъ	L	Н	N.100	Vid	Х	Н
Verify Sector Protection (2), (4)	N.1007	Lo	Н	L	Н	WL101	Vid	Code	Н
Temporary Sector Unprotection (5)	X	X	X	Х	Х	X	Х	X	Vid
Reset (Hardware)/Standby	X	Х	X	Х	Х	X	Х	HIGH-Z	L

Table 2 MBM29LV160T/B User Bus Operation (BYTE = VIII)

Table 3 MBM29LV160T/B User Bus Operation (BYTE = V⊩)

Operation	CE	ŌE	WE	DQ15 /A-1	A٥	A 1	A	A9	DQ ₀ to DQ ₇	RESET
Auto-Select Manufacture Code (1)	Ŀ	Ľ	Ho	8-E.O	Ŀſ	NL.	L	Vid	Code	H
Auto-Select Device Code (1)	L		Н	0.FC	Н	TL	L	VID	Code	HIM
Read (3)	L	VL'N	Н	A -1	Ao	A ₁	A ₆	A ₉	Dout	H.TV
Standby	Н	X	Х	X	X	X	Х	Х	HIGH-Z	HIT
Output Disable	L	H	Н	X	Х	Х	Х	Х	HIGH-Z	HM.
Write (Program/Erase)	L	Н	Ľ	A -1	Ao	A ₁	A ₆	A9	DIN	NON. HOM
Enable Sector Protection (2), (4)	L	VID	Т	4.1)0 <u>7</u> .	H	L.L	VID	X	100 H CON
Verify Sector Protection (2), (4)	L.	L	Η	L.	1051	H	MLT	Vid	Code	100 H CO
Temporary Sector Unprotection (5)	X	Х	Х	X	X	Х	Х	Х	Х	Vid
Reset (Hardware)/Standby	X	Х	Х	Х	X	Х	X	Х	HIGH-Z	W.120

Legend: $L = V_{IL}$, $H = V_{IH}$, $X = V_{IL}$ or V_{IH} . $\Box \Gamma$ = pulse input. See DC Characteristics for voltage levels.

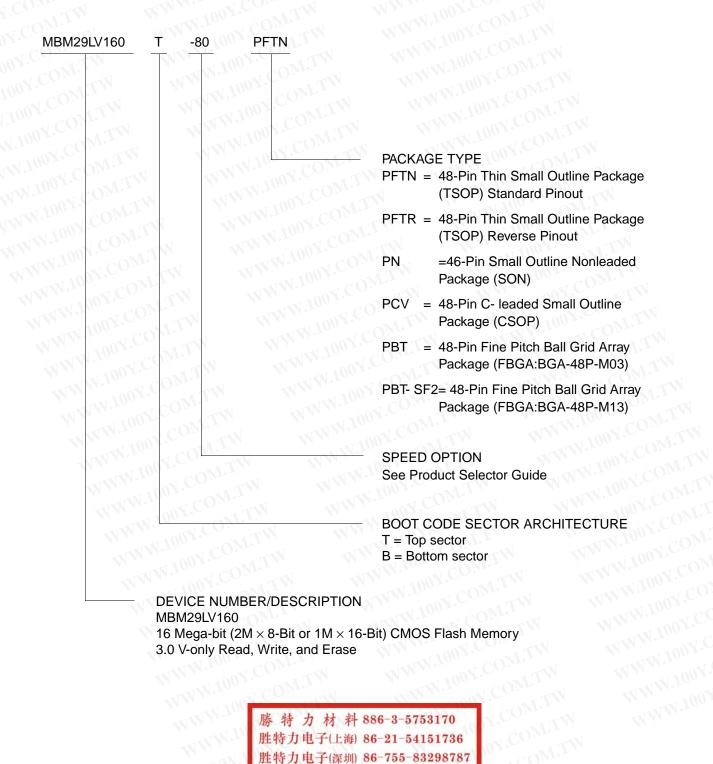
Notes: 1. Manufacturer and device codes may also be accessed via a command register write sequence. See WWW.100Y.CON Table 7.

- 2. Refer to the section on Sector Protection.
- 3. WE can be V_{IL} if \overline{OE} is V_{IL}, \overline{OE} at V_{IH} initiates the write operations.
- 4. $V_{CC} = 3.3 V \pm 10\%$
- 5. It is also used for the extended sector protection.

ORDERING INFORMATION

Standard Products

Fujitsu standard products are available in several packages. The order number is formed by a combination of:



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FUNCTIONAL DESCRIPTION

Read Mode

The MBM29LV160T/B has two control functions which must be satisfied in order to obtain data at the outputs. \overline{CE} is the power control and should be used for a device selection. \overline{OE} is the output control and should be used to gate data to the output pins if a device is selected.

Address access time (t_{ACC}) is equal to the delay from stable addresses to valid output data. The chip enable access time (t_{CE}) is the delay from stable addresses and stable \overline{CE} to valid data at the output pins. The output enable access time is the delay from the falling edge of \overline{OE} to valid data at the output pins. (Assuming the addresses have been stable for at least t_{ACC} - t_{OE} time.) See Figure 5.1 for timing specifications.

Standby Mode

There are two ways to implement the standby mode on the MBM29LV160T/B devices. One is by using both the CE and RESET pins; the other via the RESET pin only.

When using both pins, a CMOS standby mode is achieved with \overline{CE} and \overline{RESET} inputs both held at V_{cc} ±0.3 V. Under this condition the current consumed is less than 5 µA max. During Embedded Algorithm operation, V_{cc} Active current (I_{cc2}) is required even $\overline{CE} =$ "H". The device can be read with standard access time (t_{cE}) from either of these standby modes.

When using the RESET pin only, a CMOS standby mode is achieved with the RESET input held at Vss ±0.3 V ($\overline{CE} = "H"$ or "L"). Under this condition the current consumed is less than 5 µA max. Once the RESET pin is taken high, the device requires tRH of wake up time before outputs are valid for read access.

In the standby mode, the outputs are in the high-impedance state, independent of the OE input.

Automatic Sleep Mode

There is a function called automatic sleep mode to restrain power consumption during read-out of MBM29LV160T/B data. This mode can be used effectively with an application requesting low power consumption such as handy terminals.

To activate this mode, MBM29LV160T/B automatically switches itself to low power mode when addresses remain stable for 150 ns. It is not necessary to control \overline{CE} , \overline{WE} , and \overline{OE} in this mode. During such mode, the current consumed is typically 1 μ A (CMOS Level).

Standard address access timings provide new data when addresses are changed. While in sleep mode, output data is latched and always available to the system.

Output Disable

If the \overline{OE} input is at a logic high level (V_H), output from the device is disabled. This will cause the output pins to be in a high-impedance state.

Autoselect

The Autoselect mode allows the reading out of a binary code from the device and will identify its manufacturer and type. The intent is to allow programming equipment to automatically match the device to be programmed with its corresponding programming algorithm. The Autoselect command may also be used to check the status of write-protected sectors. (See Tables 4.1 and 4.2.) This mode is functional over the entire temperature range of the device.

To activate this mode, the programming equipment must force V_{ID} (11.5 V to 12.5 V) on address pin A₉. Two identifier bytes may then be sequenced from the devices outputs by toggling address A₀ from V_{IL} to V_{IH}. All addresses are DON'T CARES except A₀, A₁, and A₆ (A₋₁). (See Table 2 or Table 3.)

The manufacturer and device codes may also be read via the command register, for instances when the MBM29LV160T/B is erased or programmed in a system without access to high voltage on the A9 pin. The command sequence is illustrated in Table 7, Command Definitions.

Byte 0 ($A_0 = V_{IL}$) represents the manufacture's code and byte 1 ($A_0 = V_{IH}$) represents the device identifier code. For the MBM29LV160T/B these two bytes are given in the Table 4.2. All identifiers for manufactures and device will exhibit odd parity with DQ7 defined as the parity bit. In order to read the proper device codes when executing the Autoselect, A1 must be VIL. (See Tables 2 or 3.) For device indentification in word mode (BYTE = VIH), DQ9 and DQ13 are equal to '1' and DQ8, DQ10 to DQ12, DQ14, and DQ15 are equal to '0'.

If BYTE = VIL (for byte mode), the device code is C4H (for top boot block) or 49H (for bottom boot block). If BYTE = V_{H} (for word mode), the device code is 22C4H (for top boot block) or 2249H (for bottom boot block).

In order to determine which sectors are write protected, A1 must be at VIH while running through the sector addresses; if the selected sector is protected, a logical '1' will be output on DQ₀ (DQ₀ = 1).

W.100Y.CO	Туре	NWW.	A12 to A18	A	A 1	A	A -1*1	Code (HEX)
Manufacture's	Code	WW	X	VIL	Vil	VIL	CVIL	04H
WW.100X		Byte	VOOX.	ONL.	V	N W W. LU	VIL	C4H
WW. P. W. COMP.	MBM29LV160T	Word	X	VIL	Vı∟	Viн	X	22C4H
Device Code	evice Code	Byte	V 100	Y.COM	TW V	WWW.	VIL	49H
	MBM29LV160B	Word	X	Vil	V⊫	Vін	X	2249H
Sector Protect	ion	N	Sector Addresses	VIL	Vін	VIL	VIL	01H*2

Table 4.1 MBM29LV160T/B Sector Protection Verify Autoselect Code

*1: A-1 is for Byte mode.

*2: Outputs 01H at protected sector addresses and outputs 00H at unprotected sector addresses.

	Туре		Code	DQ 15	DQ ₁₄	DQ ₁₃	DQ ₁₂	DQ 11	DQ 10	DQ9	DQ8	DQ7	DQ ₆	DQ₅	DQ4	DQ ₃	DQ ₂	DQ1	DQ
Manufa	acture's Code	x1	04H	A-1/0	0	0	0	0	0	0	0	0	0	0	0	0	10	0	0
MBM29LV160T	(B)	C4H	A -1	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	1	1	0	0	0	1.	0	0	
Device	Device Code	(W)	22C4H	0	0	1	0	0	0	.190	0	211	1	0	0	0	11	0	0
Code		(B)	49H	A -1	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	0	1	0	0	1	0	0	1
MBM29LV160B	(W)	2249H	0	0	1	0	0	0	1	0	0	1	0	0	1	0	0	1	
Sector	Protection		01H	A-1/0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1

Table 4.2 Expanded Autoselect Code Table

(W): Word mode

Sector Address	A 19	A 18	A 17	A 16	A 15	A 14	A 13	A 12	(× 8) Address Range	(× 16) Address Range
SA0	0	0	0	0	0	Х	X	X	00000H to 0FFFFH	00000H to 07FFFH
SA1	0	0	0	0	10	Х	X	Х	10000H to 1FFFFH	08000H to 0FFFFH
SA2	0	0	0	1.100	0	X	X	Х	20000H to 2FFFFH	10000H to 17FFFH
SA3	0	0	0	V110	1	X	Х	Х	30000H to 3FFFFH	18000H to 1FFFFH
SA4	0	0	1	0.1	0	X	Х	Х	40000H to 4FFFFH	20000H to 27FFFH
SA5	0	0	1	0	19	X	Х	Х	50000H to 5FFFFH	28000H to 2FFFFH
SA6	0	0	1	1	0	Х	X	Х	60000H to 6FFFFH	30000H to 37FFFH
SA7	0	0	1	1	N10	Х	X	Х	70000H to 7FFFFH	38000H to 3FFFFH
SA8	0	1	0	0	0	X	Х	Х	80000H to 8FFFFH	40000H to 47FFFH
SA9	0	1	0	0	1	X	Х	Х	90000H to 9FFFFH	48000H to 4FFFFH
SA10	0	1	0	1	0	X	X	X	A0000H to AFFFFH	50000H to 57FFFH
SA11	0	15	0	1	1	X	X	X	B0000H to BFFFFH	58000H to 5FFFFH
SA12	0	1	1	0	0	Х	X	Х	C0000H to CFFFFH	60000H to 67FFFH
SA13	0	1	1	0	1	Х	X	Х	D0000H to DFFFFH	68000H to 6FFFFH
SA14	0	C9	1	1	0	X	X	X	E0000H to EFFFFH	70000H to 77FFFH
SA15	0	(1O)	1	1	1	X	X	X	F0000H to FFFFFH	78000H to 7FFFFH
SA16	1	0	0	0	0	X	Х	X	100000H to 10FFFFH	80000H to 87FFFH
SA17	1	0	0	0	1	X	X	X	110000H to 11FFFFH	88000H to 8FFFFH
SA18	1.1	0	0	1	0	Х	X	Х	120000H to 12FFFFH	90000H to 97FFFH
SA19	N1N.	0	0)	1	1	Х	X	Х	130000H to 13FFFFH	98000H to 9FFFFH
SA20	11	0	10	0	0	Х	X	Х	140000H to 14FFFFH	A0000H to A7FFFH
SA21	1	0.00	1	0	1	Х	X	X	150000H to 15FFFFH	A8000H to AFFFFH
SA22	1	010	1	CO11	0	Х	Х	X	160000H to 16FFFFH	B0000H to B7FFFH
SA23	1	0	09	-3N	1	X	Х	X	170000H to 17FFFFH	B8000H to BFFFFH
SA24	1	1	0	0	0	Х	X	X	180000H to 18FFFFH	C0000H to C7FFFH
SA25	1	1	0	0	1.1	Х	Х	Х	190000H to 19FFFFH	C8000H to CFFFFH
SA26	1	1	0	1	0	X	Х	Х	1A0000H to 1AFFFFH	D0000H to D7FFFH
SA27	1	1	0	001.0	1	X	Х	Х	1B0000H to 1BFFFFH	D8000H to DFFFFH
SA28	1	1	1	0	0	X	Х	X	1C0000H to 1CFFFFH	E0000H to E7FFFH
SA29	1	1	1	0	9	Х	X	X	1D0000H to 1DFFFFH	E8000H to EFFFFH
SA30	1	1	1	1.0	0	Х	X	Х	1E0000H to 1EFFFFH	F0000H to F7FFFH
SA31	1	1	1	1	01.C	0	X	Х	1F0000H to 1F7FFFH	F8000H to FBFFFH
SA32	1	1	1	1	11	<u>69</u>	0	0	1F8000H to 1F9FFFH	FC000H to FCFFFH
SA33	1	1	1	1	1		0	1	1FA000H to 1FBFFFH	FD000H to FDFFFH

WWW.100Y. Table 5 Sector Address Tables (MBM29LV160T)

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Sector Address	A 19	A 18	A 17	A 16	A 15	A 14	A 13	A 12	(× 8) Address Range	(× 16) Address Range
SA0	0	0	0	0	0	0	0	Х	00000H to 03FFFH	N 00000H to 01FFFH
SA1	0	0	0	0	0	0	1	0	04000H to 05FFFH	02000H to 02FFFH
SA2	0	0	0	0	0	0	1	1	06000H to 07FFFH	03000H to 03FFFH
SA3	0	0	0	0	0	01	0	Х	08000H to 0FFFFH	04000H to 07FFFH
SA4	0	0	0	0	1	X	Х	Х	10000H to 1FFFFH	08000H to 0FFFFH
SA5	0	0	0	1	0	X	Х	Х	20000H to 2FFFFH	10000H to 17FFFH
SA6	0	0	0	1	001.10	Х	X	Х	30000H to 3FFFFH	18000H to 1FFFFH
SA7	0	0	1	0	0	Х	Х	Х	40000H to 4FFFFH	20000H to 27FFFH
SA8	0	0	1	0	11	X	Х	Х	50000H to 5FFFFH	28000H to 2FFFFH
SA9	0	0	1	1	0	X	Х	Х	60000H to 6FFFFH	30000H to 37FFFH
SA10	0	0	1	1	1	X	Х	X	70000H to 7FFFFH	38000H to 3FFFFH
SA11	0	1	0	0 <	0	X	X	X	80000H to 8FFFFH	40000H to 47FFFH
SA12	0	1	0	0	1	Х	X	Х	90000H to 9FFFFH	48000H to 4FFFFH
SA13	0	1	0	1	0	Х	X	Х	A0000H to AFFFFH	50000H to 57FFFH
SA14	0	C9 ^N	0	1	1	X	X	X	B0000H to BFFFFH	58000H to 5FFFFH
SA15	0	(.0 0)	1	0 🗸	0	X	Х	X	C0000H to CFFFFH	60000H to 67FFFH
SA16	0	1 100	1	0	1	X	Х	X	D0000H to DFFFFH	68000H to 6FFFFH
SA17	0	10	01	1	0	X	Х	X	E0000H to EFFFFH	70000H to 77FFFH
SA18	0	1	00^{M}	1	1	X	X	Х	F0000H to FFFFFH	78000H to 7FFFFH
SA19	11	0	0	0	0	Х	X	Х	100000H to 1FFFFFH	80000H to 87FFFH
SA20	11	0	0	0	1	Х	X	Х	110000H to 11FFFFH	88000H to 8FFFFH
SA21	1	0	0	1.1	0	Х	Х	X	120000H to 12FFFFH	90000H to 97FFFH
SA22	1	0	0	011	1	Х	Х	X	130000H to 13FFFFH	98000H to 9FFFFH
SA23	1	0	09	0	0	Х	Х	Х	140000H to 14FFFFH	A0000H to A7FFFH
SA24	1	0	7001	0	1	Х	Х	X	150000H to 15FFFFH	A8000H to 8FFFFH
SA25	1 🔨	0	0.100	1	0	Х	Х	Х	160000H to 16FFFFH	B0000H to B7FFFH
SA26	1	0	10	1	1	Х	Х	Х	170000H to 17FFFFH	B8000H to BFFFFH
SA27	1	1	0	0	0	X	Х	Х	180000H to 18FFFFH	C0000H to C7FFFH
SA28	1	1	0	0	1	X	Х	Х	190000H to 19FFFFH	C8000H to CFFFFH
SA29	1	1	0	10	0	Х	X	X	1A0000H to 1AFFFFH	D0000H to D7FFFH
SA30	1	1 🔻	0	1	11	Х	X	Х	1B0000H to 1BFFFFH	D8000H to DFFFFH
SA31	1	1	11	0	0.0	Х	X	Х	1C0000H to 1CFFFFH	E0000H to E7FFFH
SA32	1	1	1	0	ofy.	X	X	Х	1D0000H to 1DFFFFH	E8000H to EFFFFH
SA33	1	1	1	1	0	X	X	Х	1E0000H to 1EFFFFH	F0000H to F7FFFH

WWW.100Y Table 6 Sector Address Tables (MBM29LV160B)

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Write

Device erasure and programming are accomplished via the command register. The command register is written by bringing \overline{WE} to V_{IL} , while \overline{CE} is at V_{IL} and \overline{OE} is at V_{IH} . Addresses are latched on the falling edge of \overline{CE} or \overline{WE} , whichever occurs later, while data is latched on the rising edge of \overline{CE} or \overline{WE} pulse, whichever occurs first. Standard microprocessor write timings are used. See Figures 6 to 8.

Refer to AC Write Characteristics and the Erase/Programming Waveforms for specific timing parameters.

Sector Protection

The MBM29LV160T/B features hardware sector protection. This feature will disable both program and erase operations in any number of sectors (0 through 34). The sector protection feature is enabled using programming equipment at the user's site. The device is shipped with all sectors unprotected.

To activate this mode, the programming equipment must force V_{ID} on address pin A₉ and control pin \overline{OE} , $\overline{CE} = V_{IL}$, A₀ = A₆ = V_{IL}, A₁ = V_{IH}. The sector addresses pins (A₁₉, A₁₈, A₁₇, A₁₆, A₁₅, A₁₄, A₁₃, and A₁₂) should be set to the sector to be protected. Tables 5 and 6 define the sector address for each of the thirty five (35) individual sectors. Programming of the protection circuitry begins on the falling edge of the \overline{WE} pulse and is terminated with the rising edge of the same. Sector addresses must be held constant during the \overline{WE} pulse. See figures 16 and 24 for sector protection waveforms and algorithm.

To verify programming of the protection circuitry, the programming equipment must force V_{ID} on address pin A₉ with \overline{CE} and \overline{OE} at V_{IL} and \overline{WE} at V_{IH}. Scanning the sector addresses (A₁₉, A₁₈, A₁₇, A₁₆, A₁₅, A₁₄, A₁₃, and A₁₂) while (A₆, A₁, A₀) = (0, 1, 0) will produce a logical "1" at device output DQ₀ for a protected sector. Otherwise the device will read 00H for an unprotected sector. In this mode, the lower order addresses, except for A₀, A₁, and A₆ are DON'T CARES. Address locations with A₁ = V_{IL} are reserved for Autoselect manufacturer and device codes. A₋₁ requires to V_{IL} in byte mode.

It is also possible to determine if a sector is protected in the system by writing an Autoselect command. Performing a read operation at the address location XX02H, where the higher order addresses pins (A₁₉, A₁₈, A₁₇, A₁₆, A₁₅, A₁₄, A₁₃, and A₁₂) represents the sector address will produce a logical "1" at DQ₀ for a protected sector. See Tables 4.1 and 4.2 for Autoselect codes.

Temporary Sector Unprotection

This feature allows temporary unprotection of previously protected sectors of the MBM29LV160T/B devices in order to change data. The Sector Unprotection mode is activated by setting the RESET pin to high voltage (12 V). During this mode, formerly protected sectors can be programmed or erased by selecting the sector addresses. Once the 12 V is taken away from the RESET pin, all the previously protected sectors will be protected again. (See Figures 18 and 25.)

Comma Sequer		Bus Write Cycles Req'd	First Write		Sec Bu Write	IS	Third Write		Fourth Read/ Cyc	Write	Fifth Write		Sixth Write	
(Notes 1, 2	2, 3, 5)	Req'd	Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data
Read/Reset (Note 6)	Word /Byte	1	хххн	F0H	01.1	N		VWV	1.1 <u>00</u> 1.1	1.00	<u>nn</u> VTN	_	_	_
Read/Reset	Word	3 🔨	555H		2AAH	E.L.	555H	FOL			T	Z		
(Note 6)	Byte	- 3	AAAH	AAH	555H	- 55H	AAAH	F0H	RA	RD	0.	W		
N COM	Word	0	555H	AAH	2AAH	C C L L	555H	0011	M.M.	Non Y.	COM.	WT		
Autoselect	Byte	- 3	AAAH	AAAH 5	555H	- 55H	AAAH	90H	WWW.		CON	WT.		
Byte/Word	Word	đ.,	555H	1.17	2AAH	OW.	555H		WW	.700	V.CO	1	N	
Program (Notes 3, 4)	Byte	4	AAAH	AAH	555H	55H	AAAH	A0H	PA	PD	ox.CO		N	
W.100	Word		555H		2AAH	CO	555H	0011	555H		2AAH	OW	555H	4.01
Chip Erase	Byte	6	AAAH	AAH	555H	- 55H	AAAH	- 80H	AAAH	AAH	555H	55H	AAH	- 10⊦
Sector Erase	Word	•	555H		2AAH	-	555H	0011	555H		2AAH	CON		201
(Note 3)	Byte	6	AAAH	AAH	555H	- 55H	AAAH	- 80H	AAAH	AAH	555H	55H	SA	30⊦
Sector Erase Suspend	Word /Byte	1	хххн	B0H	NTN.	1 <u>00</u> 7	.c <u>o</u> M	1.17	_	41	100 N.10	NY C	$0\underline{W}_{I}$	
Sector Erase Resume	Word /Byte	cOM	хххн	30H	11 11 11 11 11 11 11 11 11 11 11 11 11	N.100	V.CO	MITY	N N		WHI!	00x.	COM	1

Table 7 MBM29LV160T/B Standard Command Definitions

- Notes: 1. Address bits A_{11} to $A_{19} = X = "H"$ or "L" for all address commands except or Program Address (PA) and Sector Address (SA).
 - 2. Bus operations are defined in Tables 2 and 3.
 - 3. RA =Address of the memory location to be read.
 - PA =Address of the memory location to be programmed. Addresses are latched on the falling edge of the WE pulse.
 - SA =Address of the sector to be erased. The combination of A₁₉, A₁₈, A₁₇, A₁₆, A₁₅, A₁₄, A₁₃, and A₁₂ will uniquely select any sector.
 - 4. RD =Data read from location RA during read operation.
 - PD =Data to be programmed at location PA. Data is latched on the rising edge of WE.
 - 5. The system should generate the following address patterns: Word Mode: 555H or 2AAH to addresses Ao to A10

Byte Mode: AAAH or 555H to addresses A-1 to A10

6. Both Read/Reset commands are functionally equivalent, resetting the device to the read mode.

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Command		Bus Write		: Bus Cycle		nd Bus Cycle	Third Write	l Bus Cycle		h Bus Cycle	
Sequence		Cycles Req'd	Addr	Data	Addr	Data	Addr	Data	Addr	Data	
Set to Fast	Word	3	555H	AAH	2AAH	5 E LL	555H	204			
Mode	Byte	JAN N.1	AAAH	ААП	555H	55H	AAAH	20H		_	
Faat Dragram *1	Word	2	XXXH	AOH	PA	PD	ON.CC	NT. TW		_	
Fast Program *1	Byte	2	XXXH	A0H	PA	NWW	. Vo-	ONT	N		
Reset from Fast	Word	2	XXXH	0011	XXXH	F0H *4	V.Too.	COM	N		
Mode *1	Byte	Z	XXXH	90H	XXXH		W.100	COM		—	
Query	Word	0	55H	0011			NN.100,	V COM	No.		
Command *2	Byte	2	AAH	98H	1.1		WW.100	V CON		_	
Extended Sector	Word	4	VVVL	COLL	CD4	COLL	CD A	104	CDA .	00	
Protect *3	Byte	4	XXXH	60H	SPA	60H <	SPA	40H	SPA	SD	

MBM29LV160T/B Extended Command Definitions Table 8

SPA : Sector Address to be protected. Set sector address (SA) and $(A_6, A_1, A_0) = (0, 1, 0)$.

- SD : Sector protection verify data. Output 01H at protected sector addresses and output 00H at unprotected sector addresses.
- This command is valid while fast mode.
- *2. Addresses from system set to A₀ to A₆. The other addresses are "Don't care".
- This command is valid while $V_{ID} = \overline{RESET}$. *3.
- The data" OOH" is also acceptable. *4.

Command Definitions

Device operations are selected by writing specific address and data sequences into the command register. Writing incorrect address and data values or writing them in an improper sequence will reset the device to the read mode. Table 7 defines the valid register command sequences. Note that the Erase Suspend (BOH) and Erase Resume (30H) commands are valid only while the Sector Erase operation is in progress. Moreover both Read/Reset commands are functionally equivalent, resetting the device to the read mode. Please note that commands are always written at DQ₀ to DQ₇ and DQ₈ to DQ₁₅ bits are ignored.

Read/Reset Command

In order to return from Autoselect mode or Exceeded Timing Limits ($DQ_5 = 1$) to read mode, the read/reset operation is initiated by writing the Read/Reset command sequence into the command register. Microprocessor read cycles retrieve array data from the memory. The device remains enabled for reads until the command register contents are altered.

The device will automatically power-up in the Read/Reset state. In this case, a command sequence is not required to read data. Standard microprocessor read cycles will retrieve array data. This default value ensures that no spurious alteration of the memory contents occurs during the power transition. Refer to the AC Read Characteristics and Waveforms for specific timing parameters. (See Figure 5.1.)

Autoselect Command

Flash memories are intended for use in applications where the local CPU alters memory contents. As such, manufactures and device codes must be accessible while the device resides in the target system. PROM programmers typically access the signature codes by raising A₉ to a high voltage. However, multiplexing high voltage onto the address lines is not generally desired system design practice.

The device contains an Autoselect command operation to supplement traditional PROM programming methodology. The operation is initiated by writing the Autoselect command sequence into the command register. Following the last command write, a read cycle from address XX00H retrieves the manufacture code of 04H. A read cycle from address XX01H for ×16 (XX02H for ×8) retrieves the device code (MBM29LV160T = C4H and MBM29LV160B = 49H for ×8 mode; MBM29LV160T = 22C4H and MBM29LV160B = 2249H for ×16 mode). (See Tables 4.1 and 4.2.)

All manufactures and device codes will exhibit odd parity with DQ₇ defined as the parity bit. The sector state (protection or unprotection) will be indicated by address XX02H for ×16 (XX04H for ×8). Scanning the sector addresses (A₁₉, A₁₈, A₁₇, A₁₆, A₁₅, A₁₄, A₁₃, and A₁₂) while (A₆, A₁, A₀) = (0, 1, 0) will produce a logical "1" at device output DQ₀ for a protected sector. The programming verification should be perform margin mode verification on the protected sector. (See Tables 2 and 3.)

To terminate the operation, it is necessary to write the Read/Reset command sequence into the register and, also to write the Autoselect command during the operation, by executing it after writing the Read/Reset command sequence.

Word/Byte Programming

The device is programmed on a byte-by-byte (or word-by-word) basis. Programming is a four bus cycle operation. There are two "unlock" write cycles. These are followed by the program set-up command and data write cycles. Addresses are latched on the falling edge of \overline{CE} or \overline{WE} , whichever happens later and the data is latched on the rising edge of \overline{CE} or \overline{WE} , whichever happens later and the data is latched on the rising edge of \overline{CE} or \overline{WE} , whichever happens first. The rising edge of the last \overline{CE} or \overline{WE} (whichever happens first) begins programming. Upon executing the Embedded Program Algorithm command sequence, the system is not required to provide further controls or timings. The device will automatically provide adequate internally generated program pulses and verify the programmed cell margin. (See Figures 6 and 7.)

The automatic programming operation is completed when the data on DQ₇ is equivalent to data written to this bit at which time the device return to the read mode and addresses are no longer latched. (See Table 8, Hardware Sequence Flags.) Therefore, the device requires that a valid address be supplied by the system at this time. Hence, Data Polling must be performed at the memory location which is being programmed.

Any commands written to the chip during this period will be ignored. If hardware reset occures during the programming operation, it is impossible to guarantee whether the data being written is correct or not.

Programming is allowed in any sequence and across sector boundaries. Beware that a data "0" cannot be programmed back to a "1". Attempting to do so may either hang up the device or result in an apparent success according to the data polling algorithm but a read from read/reset mode will show that the data is still "0". Only erase operations can convert "0"s to "1"s.

Figure 20 illustrates the Embedded Program[™] Algorithm using typical command strings and bus operations.

Chip Erase

Chip erase is a six-bus cycle operation. There are two "unlock" write cycles. These are followed by writing the "set-up" command. Two more "unlock" write cycles are then followed by the chip erase command.

Chip erase does not require the user to program the device prior to erase. Upon executing the Embedded Erase Algorithm command sequence the device will automatically program and verify the entire memory for an all zero data pattern prior to electrical erase. (Preprogram Function.) The system is not required to provide any controls or timings during these operations.

The automatic erase begins on the rising edge of the last \overline{WE} pulse in the command sequence and terminates when the data on DQ₇ is "1" (See Write Operation Status section.) at which time the device returns to read mode. (See Figure 8.)

Figure 21 illustrates the Embedded Erase[™] Algorithm using typical command strings and bus operations.

Sector Erase

Sector erase is a six-bus cycle operation. There are two "unlock" write cycles, followed by writing the "set-up" command. Two more "unlock" write cycles are then followed by the Sector Erase command. The sector address (any address location within the desired sector) is latched on the falling edge of \overline{WE} , while the command (Data = 30H) is latched on the rising edge of \overline{WE} . After a time-out of 50 µs from the rising edge of the last sector erase command, the sector erase operation will begin.

Multiple sectors may be erased concurrently by writing six-bus cycle operations on Table 7. This sequence is followed with writes of the Sector Erase command to addresses in other sectors desired to be concurrently erased. The time between writes must be less than 50 μ s otherwise that command will not be accepted and erasure will start. It is recommended that processor interrupts be disabled during this time to guarantee this condition. The interrupts can be re-enabled after the last Sector Erase command is written. A time-out of 50 μ s from the rising edge of the last \overline{WE} will initiate the execution of the Sector Erase command(s). If another falling edge of the \overline{WE} occurs within the 50 μ s time-out window the timer is reset. Monitor DQ₃ to determine if the sector erase timer window is still open. (See section DQ₃, Sector Erase Timer.) Any command other than Sector Erase or Erase Suspend during this time-out period will reset the device to the read mode, ignoring the previous command string. Resetting the device once excution has begun will corrupt the data in the sector. In that case, restart the erase on those sectors and allow them to complete. (Refer to the Write Operation Status section for Sector Erase Timer operation.) Loading the sector erase buffer may be done in any sequence and with any number of sectors (0 to 34).

Sector erase does not require the user to program the device prior to erase. The device automatically programs all memory locations in the sector(s) to be erased prior to electrical erase (Preprogram Function). When erasing a sector or sectors the remaining unselected sectors are not affected. The system is not required to provide any controls or timings during these operations. (See Figure 8.)

The automatic sector erase begins after the 50 μ s time out from the rising edge of the WE pulse for the last sector erase command pulse and terminates when the data on DQ₇ is "1" (See Write Operation Status section) at which time the device returns to the read mode. Data polling must be performed at an address within any of the sectors being erased. Multiple Sector Erase Time; [Sector Program Time (Preprogramming) + Sector Erase Time] × Number of Sector Erase.

Figure 21 illustrates the Embedded Erase[™] Algorithm using typical command strings and bus operations.

Erase Suspend/Resume

The Erase Suspend command allows the user to interrupt a Sector Erase operation and then perform data reads from or program to a sector not being erased. This command is applicable ONLY during the Sector Erase operation which includes the time-out period for sector erase. The Erase Suspend command will be ignored if written during the Chip Erase operation or Embedded Program Algorithm. Writting the Erase Suspend command during the Sector Erase time-out results in immediate termination of the time-out period and suspension of the erase operation.

Writing the Erase Resume command resumes the erase operation. The addresses are "DON'T CARES" when writing the Erase Suspend or Erase Resume commands.

When the Erase Suspend command is written during the Sector Erase operation, the device will take a maximum of 20 μ s to suspend the erase operation. When the devices have entered the erase-suspended mode, the RY/ \overline{BY} output pin and the DQ₇ bit will be at logic "1", and DQ₆ will stop toggling. The user must use the address of the erasing sector for reading DQ₆ and DQ₇ to determine if the erase operation has been suspended. Further writes of the Erase Suspend command are ignored.

When the erase operation has been suspended, the device defaults to the erase-suspend-read mode. Reading data in this mode is the same as reading from the standard read mode except that the data must be read from sectors that have not been erase-suspended. Successively reading from the erase-suspended sector while the device is in the erase-suspend-read mode will cause DQ₂ to toggle. (See the section on DQ₂.)

After entering the erase-suspend-read mode, the user can program the device by writing the appropriate command sequence for Program. This Program mode is known as the erase-suspend-program mode. Again, programming in this mode is the same as programming in the regular Program mode except that the data must



be programmed to sectors that are not erase-suspended. Successively reading from the erase-suspended sector while the devices are in the erase-suspend-program mode will cause DQ_2 to toggle. The end of the erase-suspended Program operation is detected by the RY/BY output pin, Data polling of DQ₇, or the Toggle Bit (DQ₆) which is the same as the regular Program operation. Note that DQ₇ must be read from the Program address while DQ₆ can be read from any address.

To resume the operation of Sector Erase, the Resume command (30H) should be written. Any further writes of the Resume command at this point will be ignored. Another Erase Suspend command can be written after the chip has resumed erasing.

Extended Command

(1) Fast Mode

MBM29LV160T/B has Fast Mode function. This mode dispenses with the initial two unlock cycles required in the standard program command sequence writing Fast Mode command into the command register. In this mode, the required bus cycle for programming is two cycles instead of four bus cycles in standard program command. (Do not write erase command in this mode.) The read operation is also executed after exiting this mode. To exit this mode, it is necessary to write Fast Mode Reset command into the command register. (Refer to the Figure 26 Extended algorithm.) The Vcc active current is required even $\overline{CE} = V_{H}$ during Fast Mode.

(2) Fast Programming

During Fast Mode, the programming can be executed with two bus cycles operation. The Embedded Program Algorithm is executed by writing program set-up command (A0H) and data write cycles (PA/PD). (Refer to the Figure 26 Extended algorithm.)

(3) CFI (Common Flash Memory Interface)

The CFI (Common Flash Memory Interface) specification outlines device and host system software interrogation handshake which allows specific vendor-specified software algorithms to be used for entire families of devices. This allows device-independent, JEDEC ID-independent, and forward-and backward-compatible software support for the specified flash device families. Refer to CFI specification in detail.

The operation is initiated by writing the query command (98H) into the command register. Following the command write, a read cycle from specific address retrives device information. Please note that output data of upper byte (DQ₈ to DQ₁₅) is "0" in word mode (16 bit) read. Refer to the CFI code table. To terminate operation, it is necessary to write the read/reset command sequence into the register.

(4) Extended Sector Protect

In addition to normal sector protection, the MBM29LV160T/B has Extended Sector Protection as extended function. This function enable to protect sector by forcing V_{ID} on RESET pin and write a commnad sequence. Unlike conventional procedure, it is not necessary to force V_{ID} and control timing for control pins. The only RESET pin requires V_{ID} for sector protection in this mode. The extended sector protect requires V_{ID} on RESET pin. With this condition, the operation is initiated by writing the set-up command (60H) into the command register. Then, the sector addresses pins (A₁₉, A₁₈, A₁₇, A₁₆, A₁₅, A₁₄, A₁₃ and A₁₂) and (A₆, A₁, A₀) = (0, 1, 0) should be set to the sector to be protected (recommend to set V_{IL} for the other addresses pins), and write extended sector protect command (60H). A sector is typically protected in 150 µs. To verify programming of the protection circuitry, the sector addresses pins (A₁₉, A₁₈, A₁₇, A₁₆, A₁₅, A₁₄, A₁₃ and A₁₂) and (A₆, A₁, A₀) = (0, 1, 0) should be set and write a command (40H). Following the command write, a logical "1" at device output DQ₀ will produce for protect sector in the read operation. If the output data is logical "0", please repeat to write extended sector protect command (60H) again. To terminate the operation, it is necessary to set RESET pin to V_{IH}.

Write Operation Status

		Status	DQ7	DQ ₆	DQ₅	DQ₃	DQ ₂
WT.Mo-	Embedde	d Program Algorithm	DQ7	Toggle	0	0	1
	Embedde	d/Erase Algorithm	0	Toggle	0	1	Toggle
In com		Erase Suspend Read (Erase Suspended Sector)	1	N.1001.	00	0	Toggle
Progress	Erase Suspend Mode	Erase Suspend Read (Non-Erase Suspended Sector)	Data	Data	Data	Data	Data
	inio do	Erase Suspend Program (Non-Erase Suspended Sector)	DQ7	Toggle (Note 1)	0.0	0	1 (Note 2)
.Tunk.C	Embedded Program Algorithm Embedded/Erase Algorithm		V DQ7	Toggle	1001.00	0	1
Exceeded Time			0 // 7	Toggle	INTY.C	111	N/A
Limits		spend Program se Suspended Sector)	DQ7	Toggle	W.110Y.	0.1	N/A

Notes: 1. Performing successive read operations from any address will cause DQ₆ to toggle.

- 2. Reading the byte address being programmed while in the erase-suspend program mode will indicate logic "1" at the DQ2 bit. However, successive reads from the erase-suspended sector will cause DQ2 to toggle.
- 3. DQ₀ and DQ₁ are reserve pins for future use.
- 4. DQ4 is Fujitsu internal use only.

DQ7

Data Polling

The MBM29LV160T/B device features Data Polling as a method to indicate to the host that the Embedded Algorithms are in progress or completed. During the Embedded Program Algorithm, an attempt to read the devices will produce the complement of the data last written to DQ7. Upon completion of the Embedded Program Algorithm, an attempt to read the device will produce the true data last written to DQ7. During the Embedded Erase Algorithm, an attempt to read the device will produce a "0" at the DQ7 output. Upon completion of the Embedded Erase Algorithm an attempt to read the device will produce a "1" at the DQ7 output. The flowchart for Data Polling (DQ7) is shown in Figure 22.

For chip erase and sector erase, Data Polling is valid after the rising edge of the sixth WE pulse in the six-write pulse sequence. Data Polling must be performed at a sector address within any of the sectors being erased and not at a protected sector. Otherwise, the status may not be valid. Once the Embedded Algorithm operation is close to being completed, the MBM29LV160T/B data pins (DQ7) may change asynchronously while the output enable (\overline{OE}) is asserted low. This means that the device is driving status information on DQ₇ at one instant of time and then that byte's valid data at the next instant of time. Depending on when the system samples the DQ7 output, it may read the status or valid data. Even if the device has completed the Embedded Program Algorithm operation and DQ7 has a valid data, the data outputs on DQ0 to DQ6 may be still invalid. The valid data on DQ0 to DQ7 will be read on successive read attempts.

The Data Polling feature is only active during the Embedded Programming Algorithm, Embedded Erase Algorithm or sector erase time-out.

See Figure 9 for the Data Polling timing specifications and diagrams.

DQ₆

Toggle Bit I

The MBM29LV160T/B also feature the "Toggle Bit I" as a method to indicate to the host system that the Embedded Algorithms are in progress or completed.

During an Embedded Program or Erase Algorithm cycle, successive attempts to read (\overline{OE} toggling) data from the device will result in DQ₆ toggling between one and zero. Once the Embedded Program or Erase Algorithm cycle is completed, DQ₆ will stop toggling and valid data can be read on the next successive attempts. During programming, the Toggle Bit I is valid after the rising edge of the fourth WE pulse in the four write pulse sequence. For chip erase and sector erase, the Toggle Bit I is valid after the rising edge of the sixth WE pulse in the sixwrite pulse sequence. The Toggle Bit I is active during the sector time out.

In programming, if the sector being written to is protected, the toggle bit will toggle for about 2 μ s and then stop toggling without the data having changed. In erase, the device will erase all the selected sectors except for the ones that are protected. If all selected sectors are protected, the chip will toggle the Toggle Bit I for about 200 μ s and then drop back into read mode, having changed none of the data.

Either \overline{CE} or \overline{OE} toggling will cause the DQ₆ to toggle. In addition, an Erase Suspend/Resume command will cause the DQ₆ to toggle.

See Figure 10 and Figure 23 for the Toggle Bit I timing specifications and diagrams.

DQ5

Exceeded Timing Limits

 DQ_5 will indicate if the program or erase time has exceeded the specified limits (internal pulse count). Under these conditions DQ_5 will produce a "1". This is a failure condition which indicates that the program or erase cycle was not successfully completed. Data Polling is the only operating function of the device under this condition. The \overline{CE} circuit will partially power down the device under these conditions. The \overline{OE} and \overline{WE} pins will control the output disable functions as described in Tables 2 and 3.

The DQ₅ failure condition may also appear if a user tries to program a non blank location without erasing. In this case the device locks out and never completes the Embedded Algorithm operation. Hence, the system never reads a valid data on DQ₇ and DQ₆ never stops toggling. Once the device has exceeded timing limits, the DQ₅ bit will indicate a "1." Please note that this is not a device failure condition since the device was incorrectly used. If this occurs, reset the device with command sequence.

DQ₃

Sector Erase Timer

After the completion of the initial sector erase command sequence the sector erase time-out will begin. DQ₃ will remain low until the time-out is complete. Data Polling and Toggle Bit I are valid after the initial sector erase command sequence.

If Data Polling or the Toggle Bit I indicates the device has been written with a valid erase command, DQ₃ may be used to determine if the sector erase timer window is still open. If DQ₃ is high ("1") the internally controlled erase cycle has begun; attempts to write subsequent commands to the device will be ignored until the erase operation is completed as indicated by Data Polling or Toggle Bit I. If DQ₃ is low ("0"), the device will accept additional sector erase commands. To insure the command has been accepted, the system software should check the status of DQ₃ prior to and following each subsequent sector erase command. If DQ₃ is high on the second status check, the command may not have been accepted.

See Table 9: Hardware Sequence Flags.

DQ₂

Toggle Bit II

This Toggle Bit II, along with DQ_6 , can be used to determine whether the device is in the Embedded Erase Algorithm or in Erase Suspend.

Successive reads from the erasing sector will cause DQ₂ to toggle during the Embedded Erase Algorithm. If the device is in the erase-suspended-read mode, successive reads from the erase-suspended sector will cause DQ₂ to toggle. When the device is in the erase-suspended-program mode, successive reads from the byte address of the non-erase suspended sector will indicate a logic "1" at DQ₂.

DQ₆ is different from DQ₂ in that DQ₆ toggles only when the standard program or Erase, or Erase Suspend Program operation is in progress.

For example, DQ_2 and DQ_6 can be used together to determine if the erase-suspend-read mode is in progress. (DQ_2 toggles while DQ_6 does not.) See also Table 10 and Figure 19.

Furthermore, DQ₂ can also be used to determine which sector is being erased. When the device is in the erase mode, DQ₂ toggles if this bit is read from an erasing sector.

Mode	DQ7	DQ ₆	DQ ₂
Program	DQ7	Toggle	00X.00 1.TW
Erase	WWW 0 NY.COM	Toggle	Toggle
Erase Suspend Read (Erase Suspended Sector) (Note 1)	WWW.100X.CO	MANY 1 WW	Toggle
Erase-Suspend Program	DQ7	Toggle (Note 1)	1 (Note 2)

Table 10 Toggle Bit Status

Notes: 1. Performing successive read operations from any address will cause DQ6 to toggle.

2. Reading the byte address being programmed while in the erase-suspend program mode will indicate logic "1" at the DQ₂ bit. However, successive reads from the erase-suspended sector will cause DQ₂ to toggle.

RY/BY

Ready/Busy Pin

The MBM29LV160T/B provides a RY/BY open-drain output pin as a way to indicate to the host system that the Embedded Algorithms are either in progress or has been completed. If the output is low, the device is busy with either a program or erase operation. If the output is high, the device is ready to accept any read/write or erase operation. When the RY/BY pin is low, the devices will not accept any additional program or erase commands with the exception of the Erase Suspend command. If the MBM29LV160T/B is placed in an Erase Suspend mode, the RY/BY output will be high, by means of connecting with a pull-up resister to Vcc.

During programming, the RY/BY pin is driven low after the rising edge of the fourth $\overline{\text{WE}}$ pulse. During an erase operation, the RY/BY pin is driven low after the rising edge of the sixth $\overline{\text{WE}}$ pulse. The RY/BY pin will indicate a busy condition during the RESET pulse. See Figure 11 and 12 for a detailed timing diagram. The RY/BY pin is pulled high in standby mode.

Since this is an open-drain output, RY/BY pins can be tied together in parallel with a pull-up resistor to Vcc.

RESET

Hardware Reset Pin

The MBM29LV160T/B device may be reset by driving the RESET pin to V_{IL}. The RESET pin has a pulse requirement and has to be kept low (V_{IL}) for at least 500 ns in order to properly reset the internal state machine. Any operation in the process of being executed will be terminated and the internal state machine will be reset to the read mode t_{READY} after the RESET pin is driven low. Furthermore, once the RESET pin goes high, the device requires an additional t_{RH} before it allows read access. When the RESET pin is low, the device will be in the standby mode for the duration of the pulse and all the data output pins will be tri-stated. If a hardware reset occurs during a program or erase operation, the data at that particular location will be corrupted. Please note that the RY/BY output signal should be ignored during the RESET pulse. Refer to Figure 12 for the timing diagram. Refer to Temporary Sector Unprotection for additional functionality.

If hardware reset occurs during Embedded Erase Algorithm, there is a possibility that the erasing sector(s) will need to be erased again before they can be programmed.

Word/Byte Configuration

The BYTE pin selects the byte (8-bit) mode or word (16-bit) mode for the MBM29LV160T/B device. When this pin is driven high, the device operates in the word (16-bit) mode. The data is read and programmed at DQ₀ to DQ₁₅. When this pin is driven low, the device operates in byte (8-bit) mode. Under this mode, DQ₁₅/A-1 pin becomes the lowest address bit and DQ₈ to DQ₁₄ bits are tri-stated. However, the command bus cycle is always an 8-bit operation and hence commands are written at DQ₀ to DQ₇ and DQ₈ to DQ₁₅ bits are ignored. Refer to Figures 13 and 14 for the timing diagrams.

Data Protection

The MBM29LV160T/B is designed to offer protection against accidental erasure or programming caused by spurious system level signals that may exist during power transitions. During power up the device automatically resets the internal state machine to the Read mode. Also, with its control register architecture, alteration of the memory contents only occurs after successful completion of specific multi-bus cycle command sequence.

The device also incorporates several features to prevent inadvertent write cycles resulting form Vcc power-up and power-down transitions or system noise.

Low Vcc Write Inhibit

To avoid initiation of a write cycle during V_{CC} power-up and power-down, a write cycle is locked out for V_{CC} less than 2.3 V (typically 2.4 V). If V_{CC} < V_{LKO}, the command register is disabled and all internal program/erase circuits are disabled. Under this condition, the device will reset to the read mode. Subsequent writes will be ignored until the V_{CC} level is greater than V_{LKO}. It is the users responsibility to ensure that the control pins are logically correct to prevent unintentional writes when V_{CC} is above 2.3 V.

If the Embedded Erase Algorithm is interrupted, there is possibility that the erasing sector(s) will need to be erased again prior to programming.

Write Pulse "Glitch" Protection

Noise pulses of less than 5 ns (typical) on OE, CE, or WE will not change the command registers.

Logical Inhibit

Writing is inhibited by holding any one of $\overline{OE} = V_{IL}$, $\overline{CE} = V_{IH}$, or $\overline{WE} = V_{IH}$. To initiate a write, \overline{CE} and \overline{WE} must be a logical zero while \overline{OE} is a logical one.

Power-up Write Inhibit

Power-up of the devices with $\overline{WE} = \overline{CE} = V_{\parallel}$ and $\overline{OE} = V_{\parallel}$ will not accept commands on the rising edge of \overline{WE} . The internal state machine is automatically reset to read mode on power-up.

Handling of SON Package

The metal portion of marking side is connected with internal chip electrically. Please pay attention not to occur electrical connection during operation. In worst case, it may be caused permanent damage to device or system by excessive current.

Description	Ao to Ao	DQ ₀ to DQ ₁₅	Description	A ₀ to A ₆	DQ ₀ to DQ ₁
Query-unique ASCII string "QRY"	10h 11h 12h	0051h 0052h 0059h	Erase Block Region 1 Information	2Dh 2Eh 2Fh	0000h 0000h 0040h
Primary OEM Command Set 2h: AMD/FJ standard type	13h 14h	0002h 0000h	Erase Block Region 2	30h 31h	0000h 0001h
Address for Primary Extended Table	Primary 15h 0040h Inform		Information	32h 33h 34h	0000h 0020h 0000h
Alternate OEM Command Set (00h = not applicable)	17h 18h	0000h 0000h	Erase Block Region 3 Information	35h	0000h
Address for Alternate OEM Extended Table	19h 1Ah	0000h 0000h	Information	36h 37h 38h	0000h 0080h 0000h
Vcc Min. (write/erase) D7-4: volt, D3-0: 100 mvolt	1Bh	0027h	Erase Block Region 4 Information	39h 3Ah	001Eh 0000h
Vcc Max. (write/erase) D7-4: volt, D3-0: 100 mvolt	1Ch	0036h	M.W. WILL	3Bh 3Ch	0000h 0001h
VPP Min. voltage	1Dh	0000h	Query-unique ASCII string	40h	0050h
VPP Max. voltage	1Eh 🔨	0000h	"PRI"	41h	0052h
Typical timeout per single byte/word write 2 ^N μs	1Fh	0004h	Major version number, ASCII	42h 43h	0049h 0031h
Typical timeout for Min. size buffer write $2^{N} \mu s$	20h	0000h	Minor version number, ASCII Address Sensitive Unlock	44h 45h	0030h 0000h
Typical timeout per individual block erase 2 ^N ms	21h	000Ah	0 = Required 1 = Not Required	WW.100Y	COMI
Typical timeout for full chip erase 2^{N} ms	22h	0000h	Erase Suspend 0 = Not Supported	46h	0002h
Max. timeout for byte/word write 2^{N} times typical	23h	0005h	1 = To Read Only 2 = To Read & Write	WWW.	01.00 001.00
Max. timeout for buffer write 2 ^N times typical	24h	0000h	Sector Protect 0 = Not Supported X = Number of sectors in per	47h	0001h
Max. timeout per individual block erase 2 ^N times typical	25h	0004h	group Sector Temporary Unprotect	48h	0001h
Max. timeout for full chip erase 2^{N} times typical	26h	0000h	00 = Not Supported 01 = Supported	WY	W.100Y
Device Size = 2 ^N byte	27h	0015h	Reserve	49h 🔨	XXXXh
Flash Device Interface description	28h 29h	0002h 0000h	WWW.100Y.COM.T	4Ah 4Bh 4Ch	XXXXh XXXXh XXXXh
Max. number of byte in multi-byte write = 2^{N}	2Ah 2Bh	0000h 0000h	WWW.100Y.COM	<u>r</u> N	XXXXII
Number of Erase Block Regions within device	2Ch	0004h	勝特力材料8	86-3-57531	70

WWW.100Y.COM

WWW.100Y.COM.TW

WWW.IC

WWW.100Y.CO NWW.100Y.C Table 11 Common Flash Memory Interface Code

■ ABSOLUTE MAXIMUM RATINGS

Storage Temperature	–55°C to +125°C
	ed–40°C to +85°C
	except A ₉ , OE, and RESET (Note 1)–0.5 V to +Vcc +0.5 V
Vcc (Note 1)	–0.5 V to +5.5 V
	–0.5 V to +13.0 V

- Notes: 1. Minimum DC voltage on input or I/O pins are -0.5 V. During voltage transitions, inputs may negative overshoot Vss to -2.0 V for periods of up to 20 ns. Maximum DC voltage on output and I/O pins are Vcc +0.5 V. During voltage transitions, outputs may positive overshoot to Vcc +2.0 V for periods of up to 20 ns.
 - 2. Minimum DC input voltage on A₉, OE, and RESET pins are -0.5 V. During voltage transitions, A₉, OE, and RESET pins may negative overshoot Vss to -2.0 V for periods of up to 20 ns. Maximum DC input voltage on A₉, OE, and RESET pins are +13.0 V which may positive overshoot to 14.0 V for periods of up to 20 ns. Voltage difference between input voltage and supply voltage (V_{IN} V_{CC}) do not exceed 9 V.
- WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

RECOMMENDED OPERATING RANGES

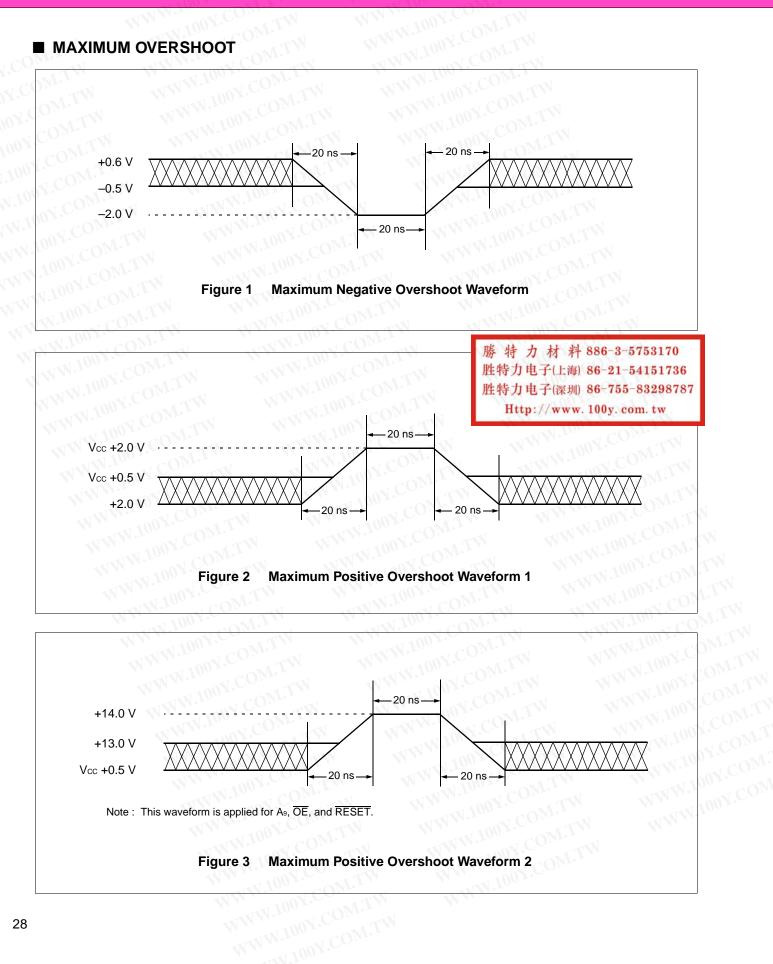
Ambient Temperature (T _A)	
MBM29LV160T/B-80	–20°C to +70°C
MBM29LV160T/B-90/-12	–40°C to +85°C
Vcc Supply Voltages	
MBM29LV160T/B-80	+3.0 V to +3.6 V
MBM29LV160T/B-90/-12	+2.7 V to +3.6 V

Operating ranges define those limits between which the functionality of the device is quaranteed.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.



DC CHARACTERISTICS

Parameter Symbol	Parameter Description	Test Conditions		Min.	Max.	Unit
Jur W	Input Leakage Current	VIN = Vss to Vcc, Vcc = Vcc	Max.	-1.0	+1.0	μA
ILO	Output Leakage Current	Vout = Vss to Vcc, Vcc = V	cc Max.	-1.0	+1.0	μA
y.clorM.T	A ₉ , OE, RESET Inputs Leakage Current	Vcc <u>= Vcc Max.,</u> A ₉ , OE, RESET = 12.5 V	100X.C	OM.TW	35	μA
OX.COM	TW WWW.100Y.CC	$\overline{CE} = V_{IL}, \overline{OE} = V_{IH}$	Byte	COM.T	30	mA
NOY.COM	Vcc Active Current (Note 1)	f = 10 MHz	Word	L.M.	35	
Icc1		$\overline{CE} = V_{IL}, \overline{OE} = V_{IH}$	Byte	Y.COM	15	mA
	MITH WWW.1005	f = 5 MHz	Word	107. <u>-</u>	17	ША
Icc2	Vcc Active Current (Note 2)	$\overline{CE} = V_{IL}, \overline{OE} = V_{IH}$	W	00 <u>1.</u> 00	35	mA
Іссз	Vcc Current (Standby)	$\frac{V_{CC} = V_{CC} \text{ Max., } \overline{CE} = V_{CC}}{\overline{RESET} = V_{CC} \pm 0.3 \text{ V}}$	±0.3 V,	.1007.C	5	μA
Icc4	Vcc Current (Standby, RESET)	Vcc = Vcc Max., RESET = Vss ±0.3 V	WW	W.100Y.	5	γµΑ
Icc5	Iccs V _{cc} Current (Automatic Sleep Mode) (Note 3) $V_{cc} = V_{cc} Max., \overline{CE} = V_{ss} \pm 0.3 V, \overline{RESET} = V_{cc} \pm 0.3 V, V_{IN} = V_{cc} \pm 0.3 V \text{ or } V_{ss} \pm 0.3 V$			M.M. 100.	5	μA
Vı∟	Input Low Level	W.L. 100Y.COM	-	-0.5	0.6	V
ViH	Input High Level	WWW. 100Y.COM.TW		2.0	Vcc + 0.3	V
Vid	Voltage for Autoselect,Sector Protection, and Temporary Sector Unprotection (A9, OE, RESET) (Note 4)	WWW.100X.COM.T WWW.100X_COM.T	LM M	11.5	12.5	V
Vol	Output Low Voltage Level	IoL = 4.0 mA, Vcc = Vcc M	n. 1	-111	0.45	V
V _{OH1}	Outrast High Malta and Lovel	Іон = -2.0 mA, Vcc = Vcc I	/lin.	2.4 🔨	100 NI	V
V _{OH2}	Output High Voltage Level	Іон = —100 µА	MIT	Vcc-0.4	N.10	V
Vlko	Low Vcc Lock-Out Voltage	WWW -100Y.C	T.Mo.	2.3	2.5	V

Notes: 1. The loc current listed includes both the DC operating current and the frequency dependent component. WWW.100Y.COM.TV

- 2. Icc active while Embedded Erase or Embedded Program is in progress.
- WWW.100Y.COM.T 3. Automatic sleep mode enables the low power mode when address remain stable for 150 ns.
- 4. $(V_{ID} V_{CC})$ do not exceed 9 V.

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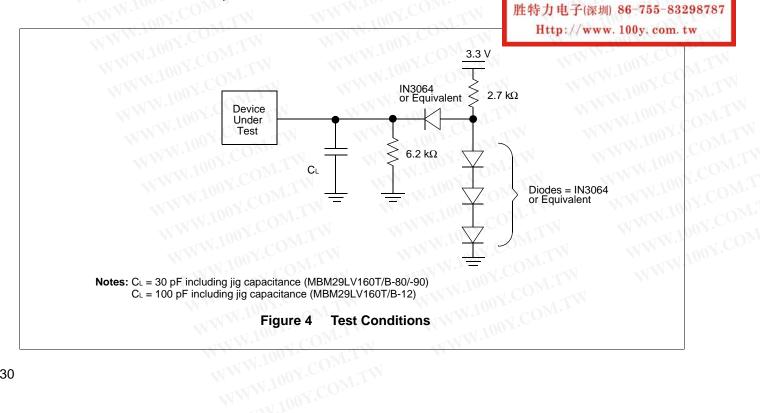
WWW.100Y.C

AC CHARACTERISTICS

	meter nbols	Description	Test Se	etup	-80	-90	-12 (Note)	Unit
JEDEC	Standard		WW	N.100	(Note)	(Note)	(NOLE)	
tavav	trc	Read Cycle Time	<u>Nu</u>	Min.	80	90	120	ns
tavqv	tacc	Address to Output Delay	$\frac{\overline{CE}}{OE} = V_{IL}$	Max.	80	90	120	ns
t ELQV	tce	Chip Enable to Output Delay	$\overline{OE} = V_{IL}$	Max.	80	90	120	ns
tGLQV	toe	Output Enable to Output Delay	_	Max.	30	35	50	ns
t ehqz	tDF	Chip Enable to Output HIGH-Z	_	Max.	25	30	30	ns
t GHQZ	tDF	Output Enable to Output HIGH-Z		Max.	25	30	30	ns
taxqx	tон	Output Hold Time From Address, CE or OE, Whichever Occurs First	1.17	Min.	0	0	0	ns
<u>4.</u>	tREADY	RESET Pin Low to Read Mode	MITN	Max.	20	20	20	μs
M M M	telfl telfh	CE or BYTE Switching Low or High	OM.TW	Max.	5	5	5	ns

Note: Test Conditions: Output Load: 1 TTL gate and 30 pF (MBM29LV160T/B-80/-90) 1 TTL gate and 100 pF (MBM29LV160T/B-12)

Input rise and fall times: 5 ns Input pulse levels: 0.0 V to 3.0 V Timing measurement reference level Input: 1.5 V Output: 1.5 V



Write (Erase/Program) Operations

Paramete	er Symbols	AW.1001.COM.17	WW.100	~ CO	MBM29LV160T/B			
JEDEC	Standard	Description		JI	-80	-90	-12	– Unit
tavav	twc	Write Cycle Time	WWW.I	Min.	80	90	120	ns
tavwl	tas	Address Setup Time	WWW.	Min.	0	0	0	ns
twLAX	tан	Address Hold Time	MMN	Min.	45	45	50	ns
tovwн	tos	Data Setup Time	MM	Min.	35	45	50	ns
t whdx	tон	Data Hold Time	MA	Min.	000	0	0	ns
100×.CC	toes	Output Enable Setup Time	N	Min.	0	0	0	ns
N 100Y.C	WT.IM	Output Enable Read	-	Min.	0	0	0	ns
N.100Y.	toeн	Hold Time Toggle and Data Pollin	וg	Min.	10	10	10	ns
t GHWL	t GHWL	Read Recover Time Before Write		Min.	0	00	0	ns
tghel	tghel	Read Recover Time Before Write (OE High to CE Low)	WT.1	Min.	0	000	0	ns
telwl	tcs	CE Setup Time	M.TW	Min.	0	0	0 0	ns
twlel	tws	WE Setup Time	DM.TW	Min.	0	0	001.1	ns
twнен	tсн	CE Hold Time	OMIN	Min.	0	0	COM	ns
tенwн	twн	WE Hold Time	COM.T	Min.	0	0	(O)	ns
t wLwH	twp	Write Pulse Width		Min.	35	45	50	ns
tеleн	tcp	CE Pulse Width	N.COM.	Min.	35	45	50	ns
t wнw∟	twpн	Write Pulse Width High	MY.COM	Min.	25	25	30	ns
t ehel	tсрн	CE Pulse Width High	NOY.COT	Min.	25	25	30	ns
1	MMM.		Byte	-17	8 🕅	8	8	
twhwh1	twhwh1	Programming Operation	Word	Тур.	16	16	16	– µs
t whwh2	twhwh2	Sector Erase Operation (Note 1)	W.100Y.	Тур.	.11	1	1.1	sec
	teoe	Delay Time from Embedded Output Er	nable	Max.	30	35	50	ns
	tvcs	Vcc Setup Time	W.100	Min.	50	50	50	μs
	tvlht	Voltage Transition Time (Note 2)	N.W.M.	Min.	4	4	4	μs
	twpp	Write Pulse Width (Note 2)	NWW.	Min.	100	100	100	μs
	toesp	OE Setup Time to WE Active (Note 2)	WWW	Min.	4	4	4	μs
	tcsp	\overline{CE} Setup Time to \overline{WE} Active (Note 2)	WW	Min.	4	4	4	μs
	t _{RB}	Recover Time From RY/BY	WW	Min.	0	0	0	ns

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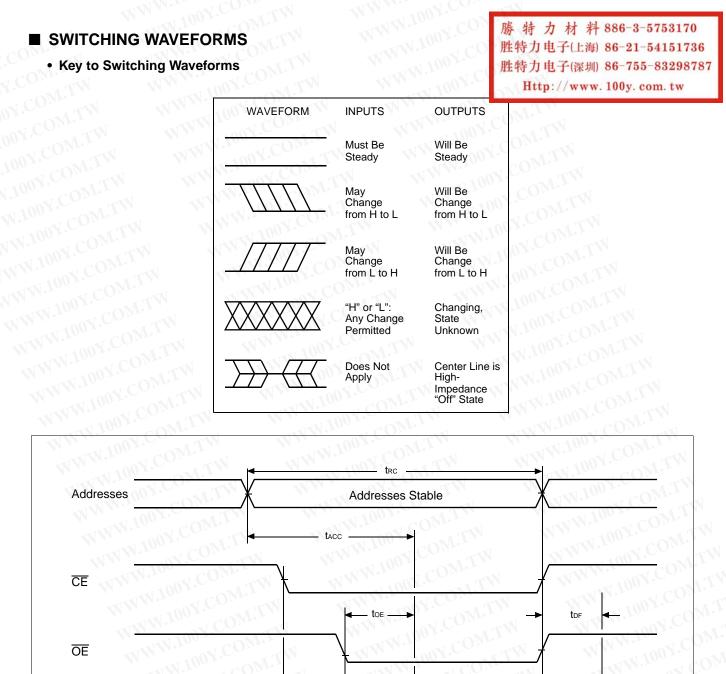
Parameter Symbols		WW.100 A. COM. I Destinitation of WW.10	N.C	МВ	M29LV16	0T/B
JEDEC	Standard	Description	00 1.	-80	-90	-12
COM.1	t _{RH}	RESET Hold Time Before Read	Min.	200	200	20
COM.	t BUSY	Program/Erase Valid to RY/BY Delay	Max.	90	90	90
N.COM	t FLQZ	BYTE Switching Low to Output HIGH-Z	Max.	30	35	50
NY.CON	t FHQV	BYTE Switching High to Output Active	Min.	30	35	50
NO I. CO	tvidr	Rise Time to V _{ID} (Note 2)	Min.	500	500	50
100¥.C	t RP	RESET Pulse Width	Min.	500	500	50

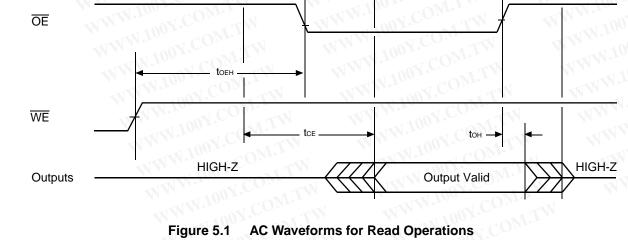
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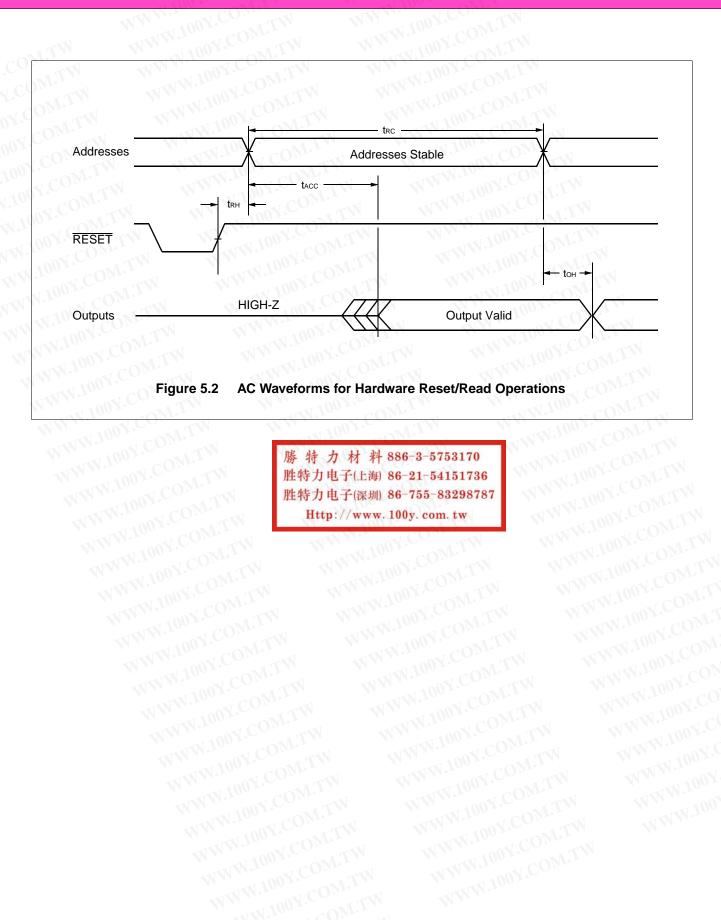
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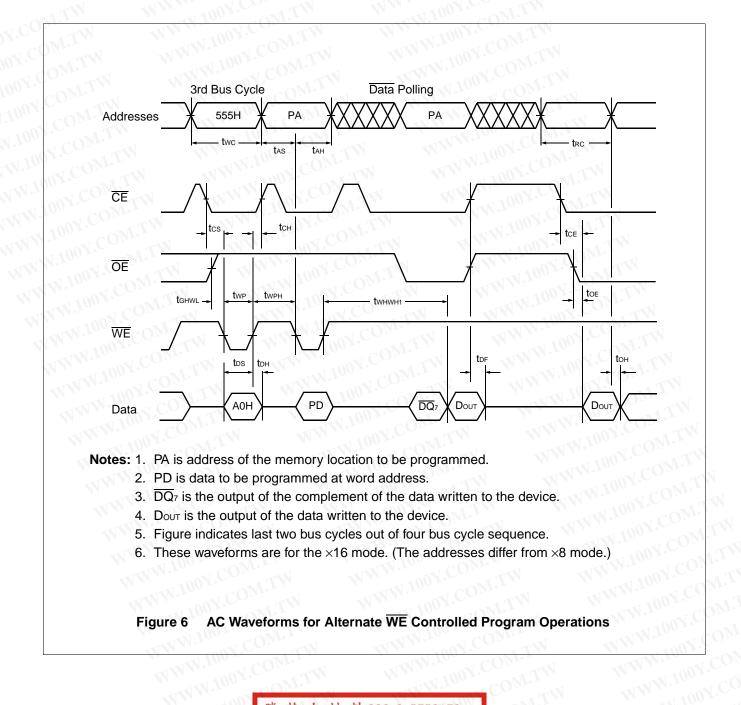
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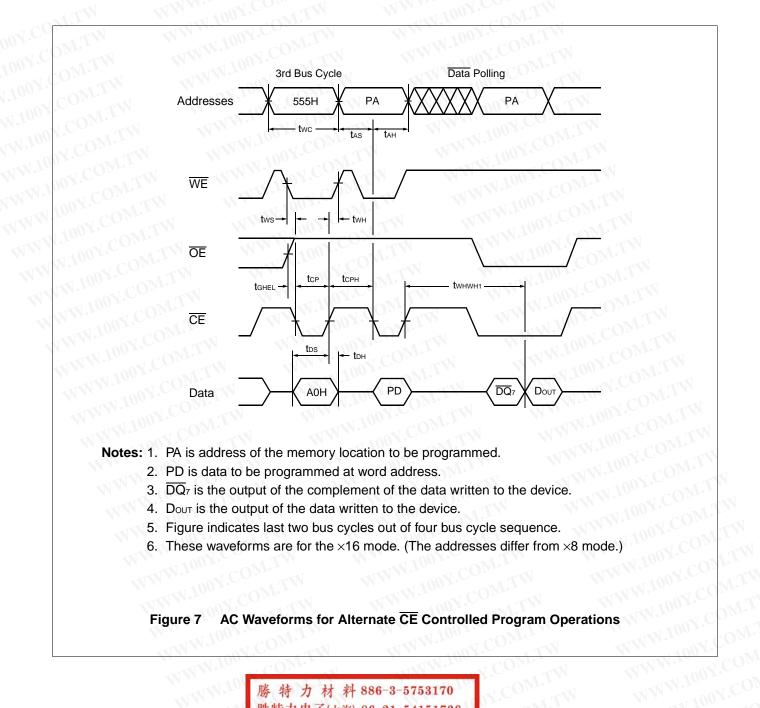
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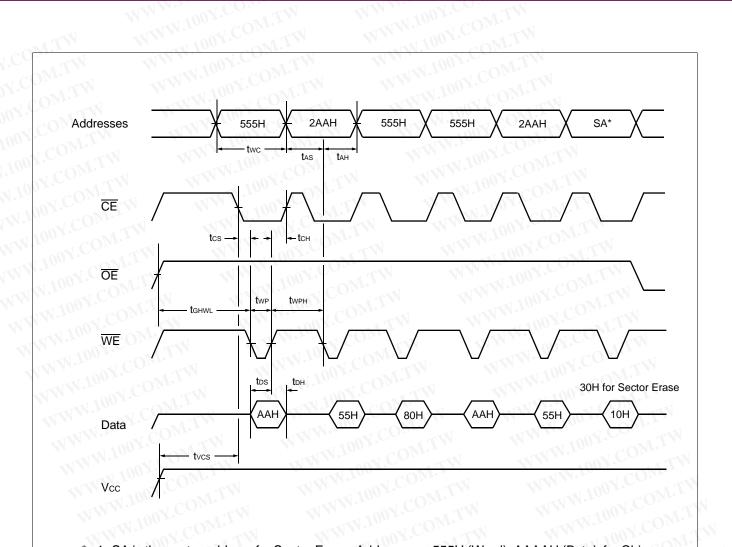
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WWW.100



- *: 1. SA is the sector address for Sector Erase. Addresses = 555H (Word), AAAAH (Byte) for Chip WWW.100Y.COM Erase.
 - 2. These waveforms are for the ×16 mode. (The addresses differ from ×8 mode.)

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WWW.100Y.C Figure 8 AC Waveforms for Chip/Sector Erase Operations

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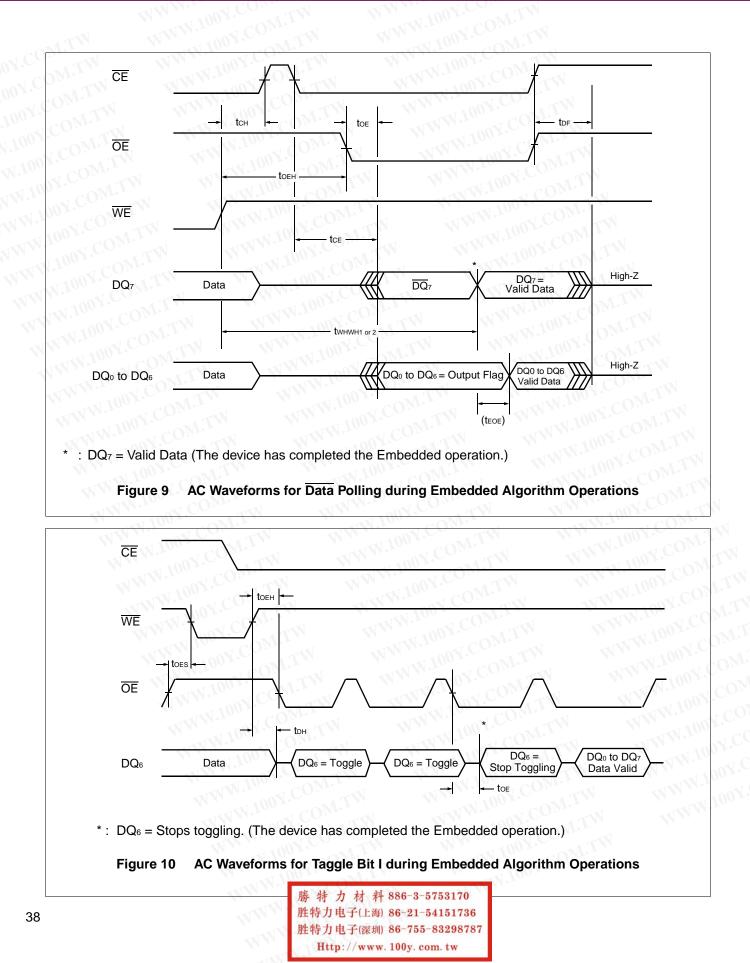
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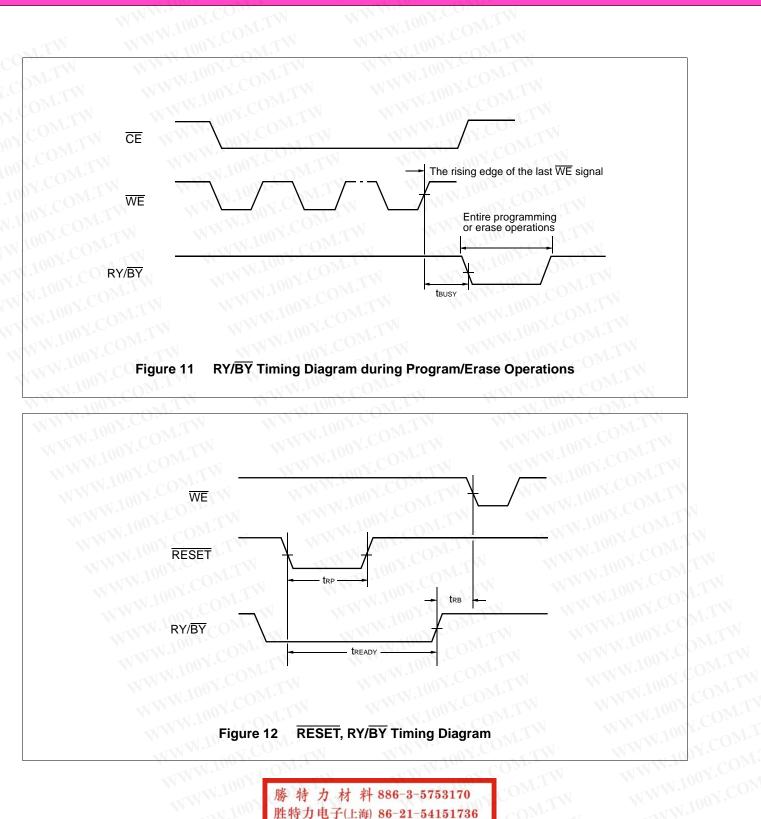
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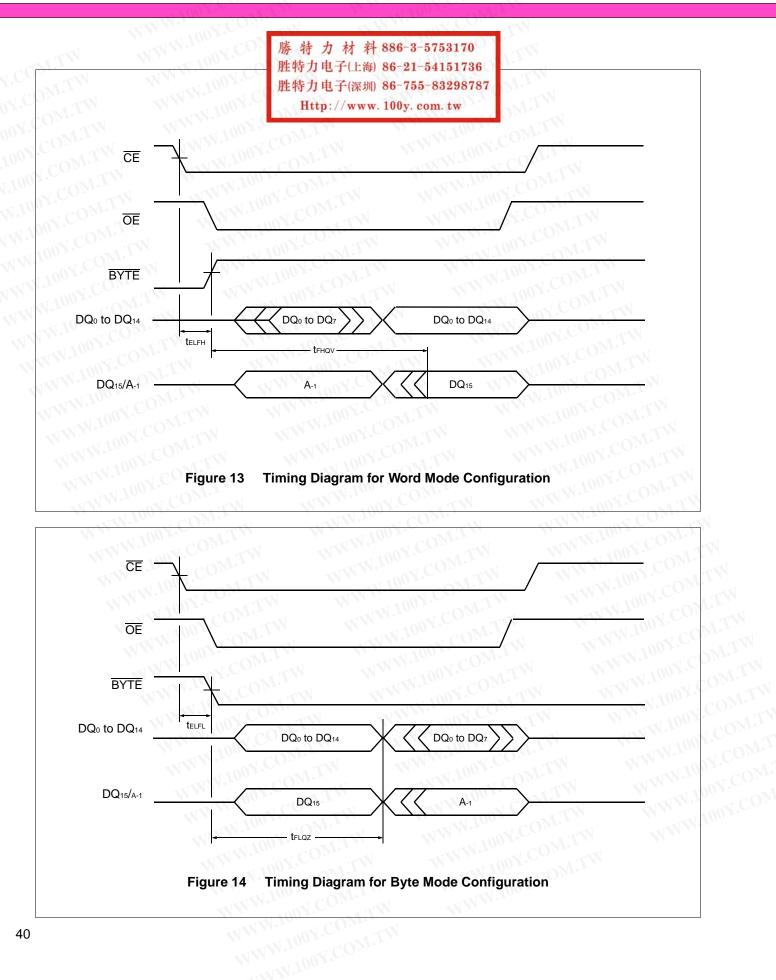


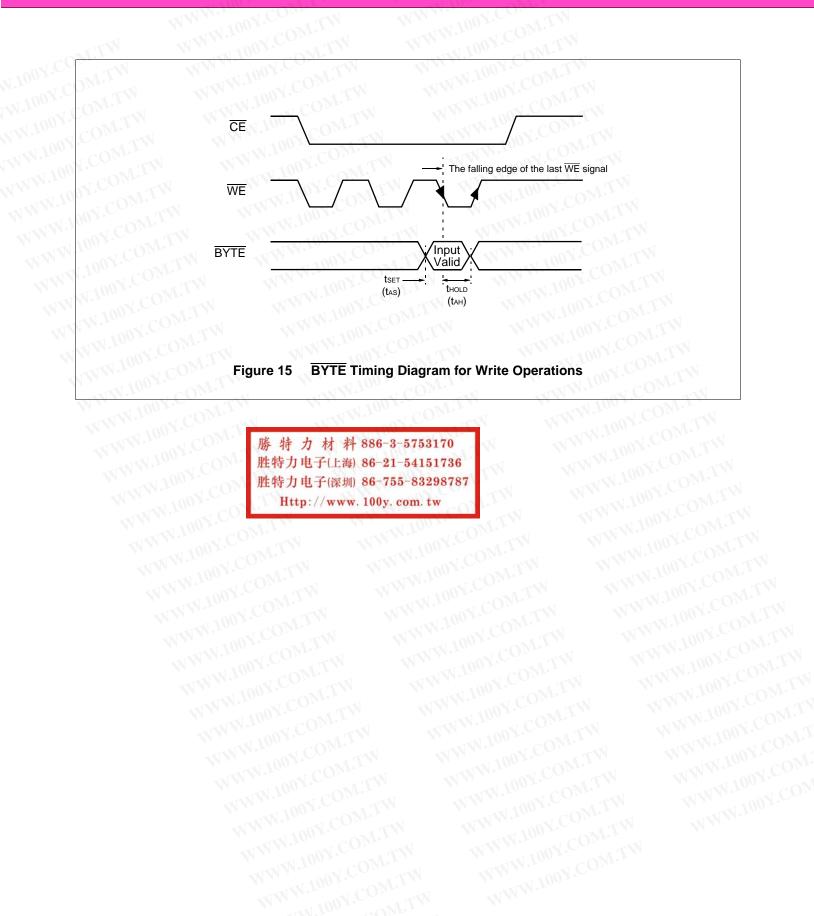
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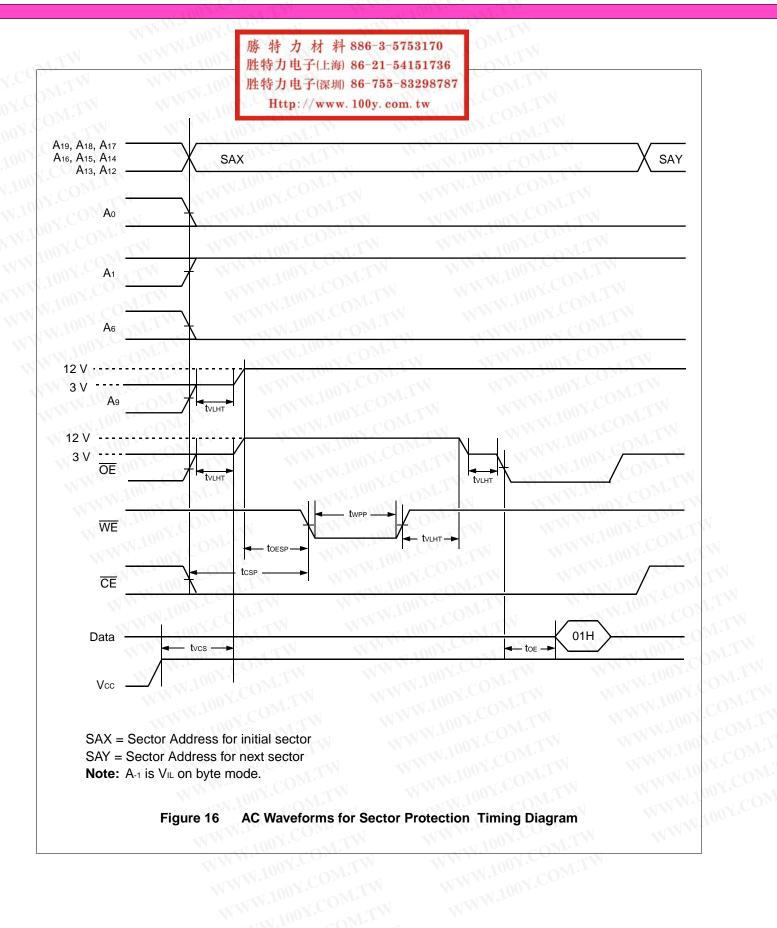
Http://www.100y.com.tw

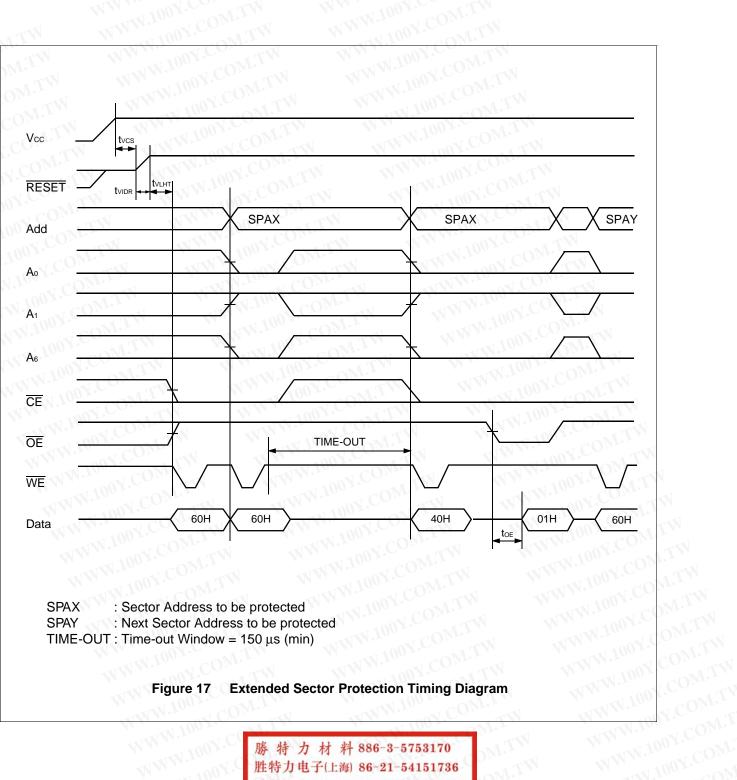
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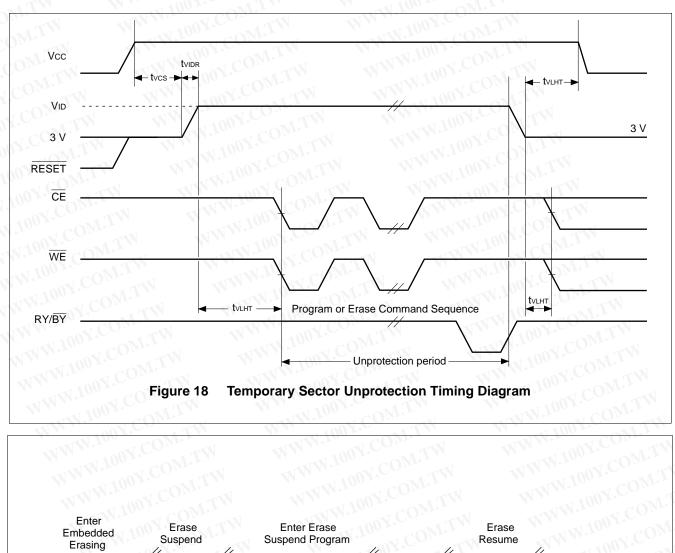


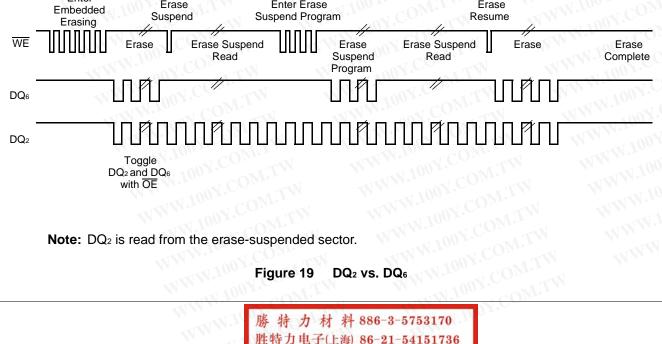




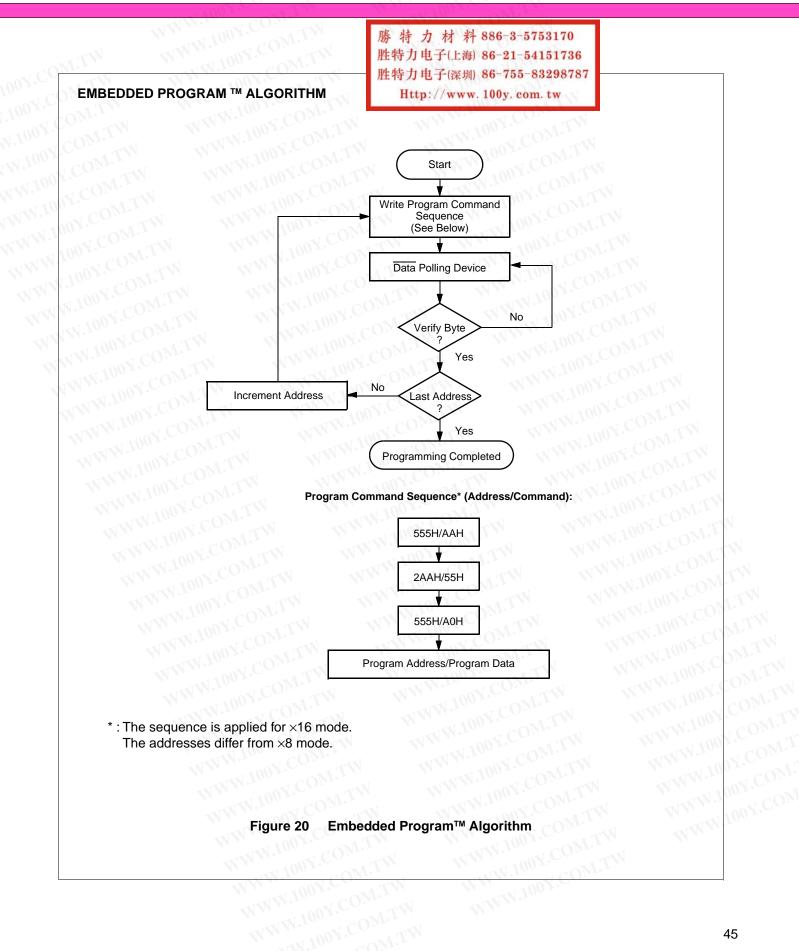
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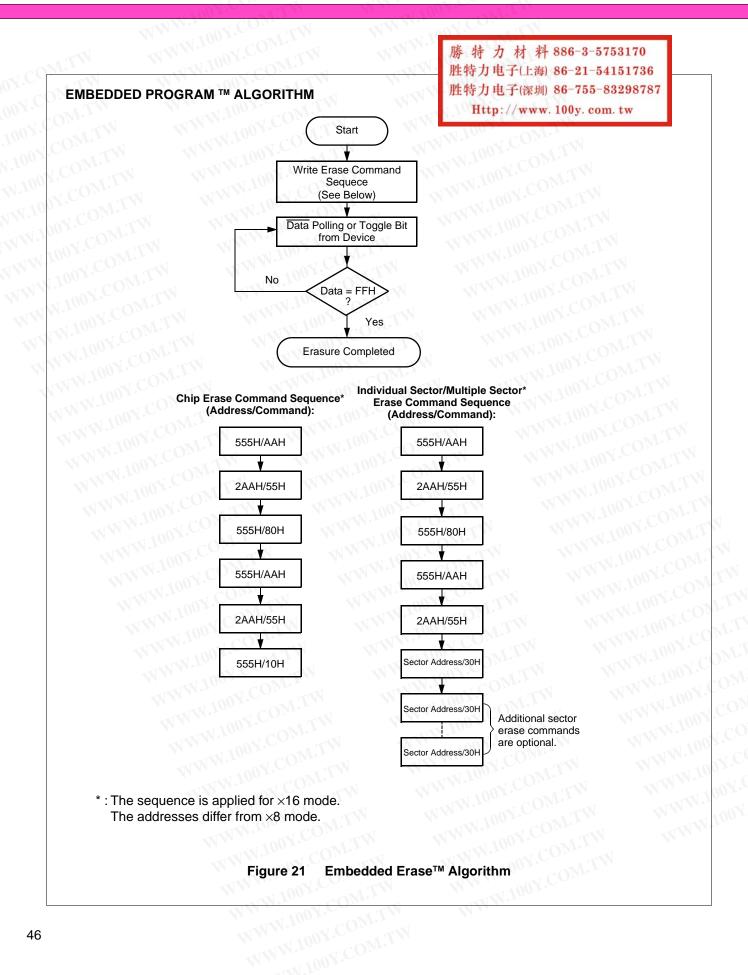
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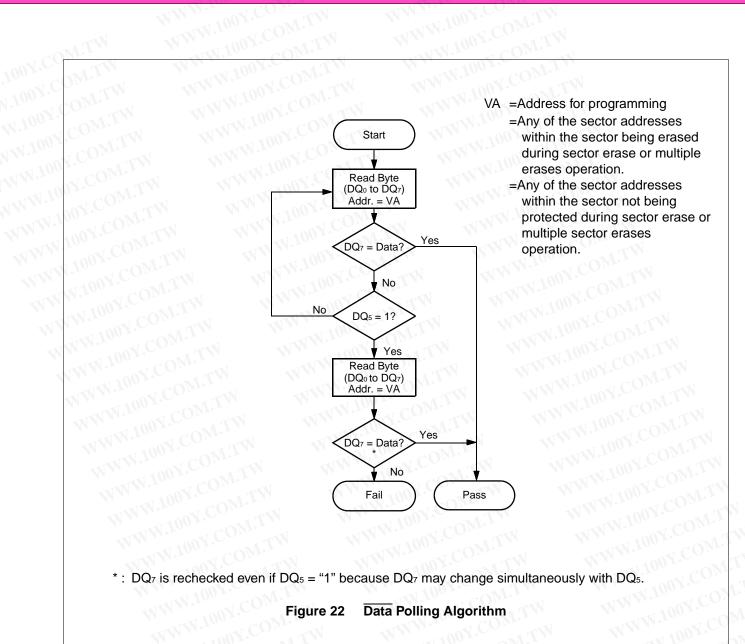


Figure 22 **Data Polling Algorithm**

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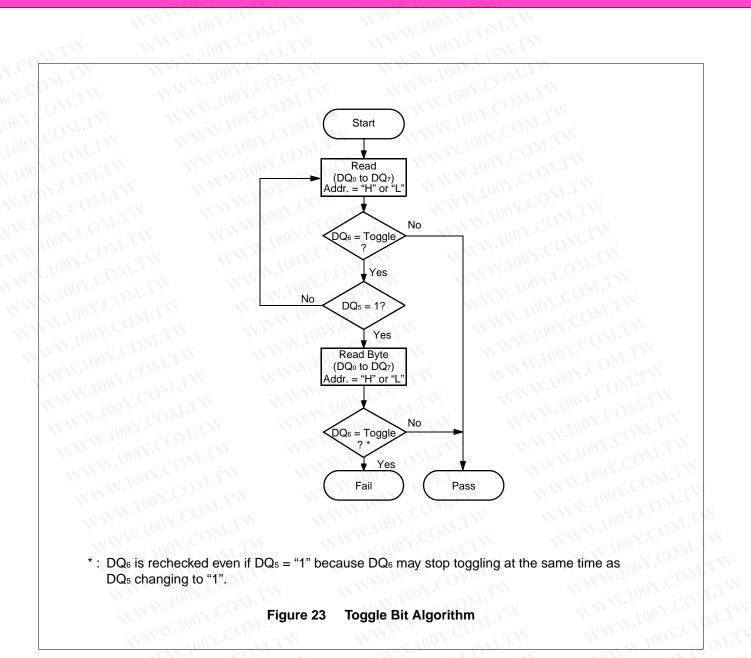
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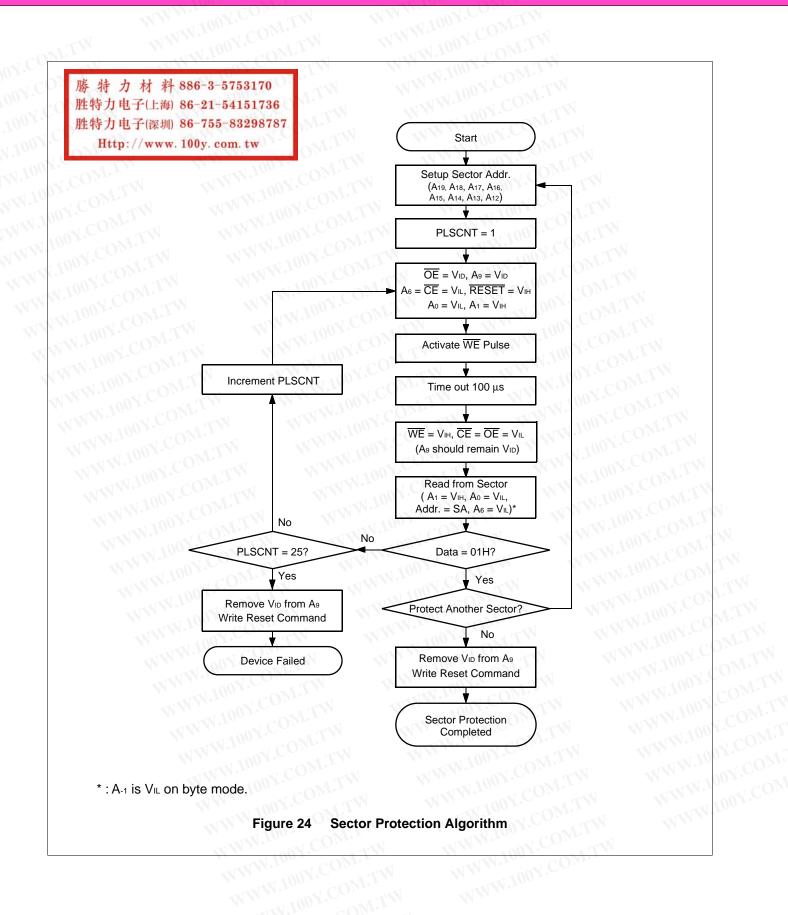
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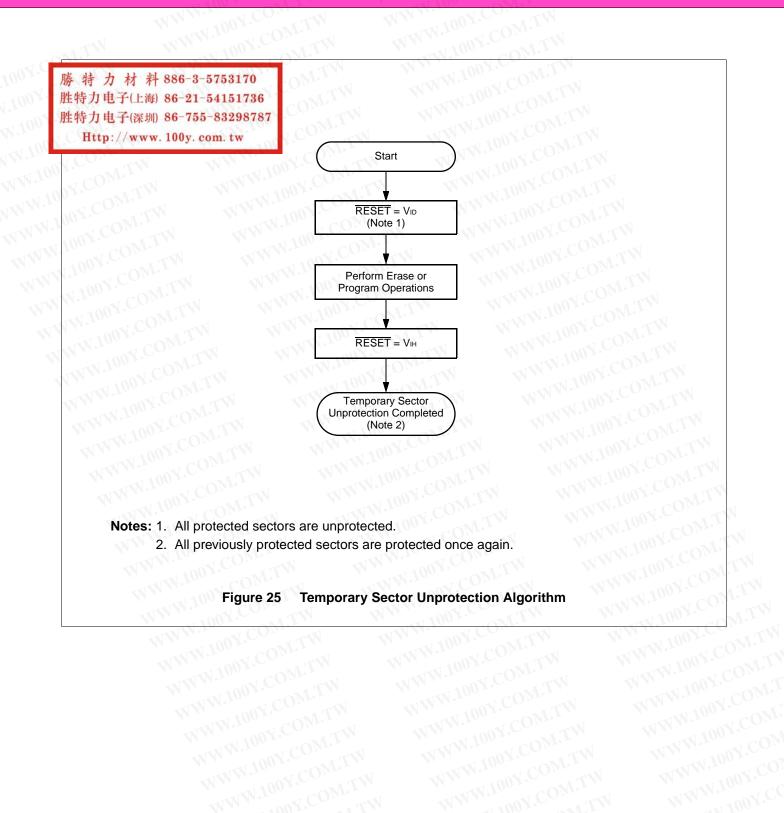
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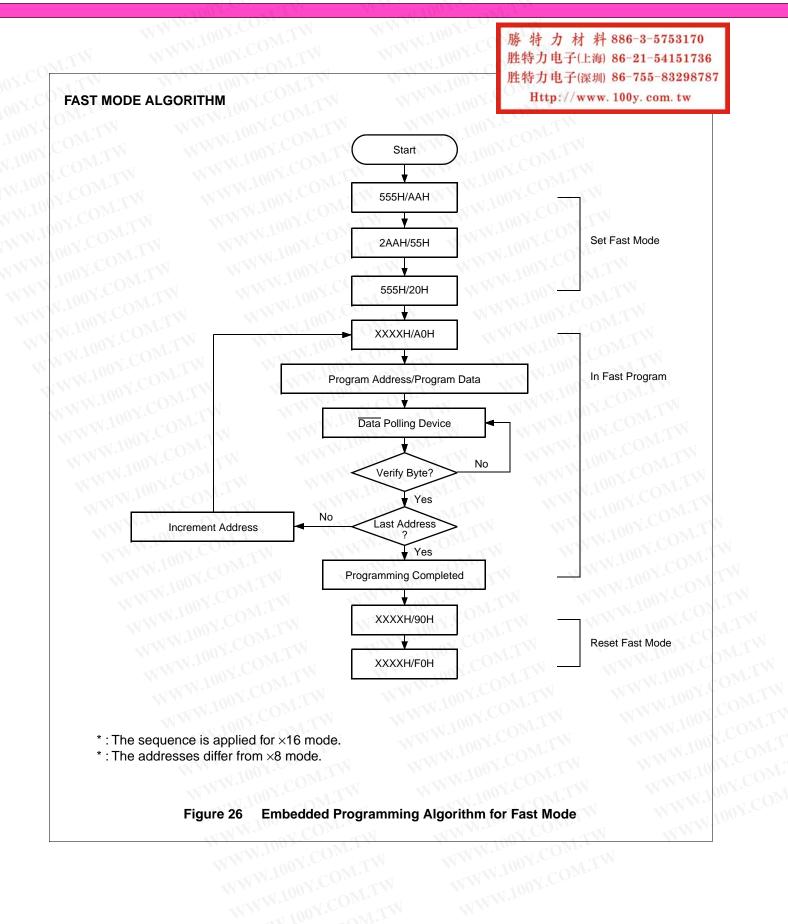
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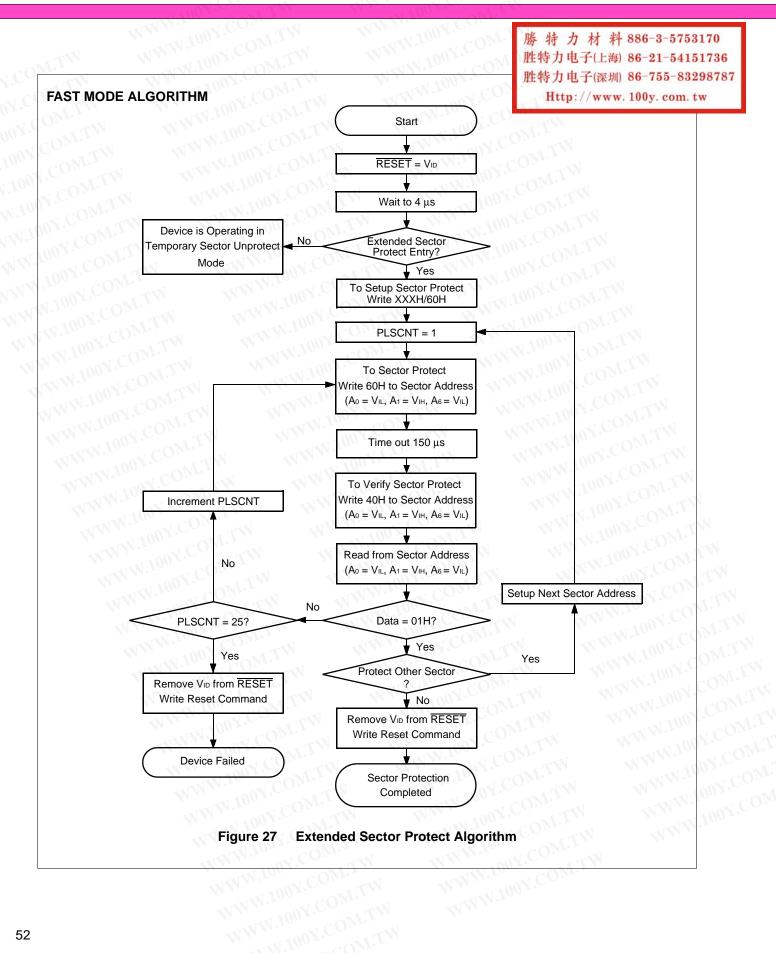
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ERASE AND PROGRAMMING PERFORMANCE

Parameter	N.COM.	Limits		Unit	Comments
Parameter	Min.	Тур.	Max.		Comments
Sector Erase Time	V.100X.COM	TW 1	10	sec	Excludes programming time prior to erasure
Byte Programming Time	N 100 T. COI	8	300	100 .	Excludes system-level
Word Programming Time	W.100	16	360	μs	overhead
Chip Programming Time	WW.100X.C	16.8	50	sec	Excludes system-level overhead
Erase/Program Cycle	100,000	TW ONL		cycles	COM.T.

■ TSOP (I) PIN CAPACITANCE

Parameter Symbol	Parameter Description	Test Setup	Тур.	Max.	Uni
CIN	Input Capacitance	V _{IN} = 0	7.5	9.5	pF
Соит	Output Capacitance	Vout = 0	8	10	pF
	Control Pin Capacitance	V _{IN} = 0	10	13	pF

SON PIN CAPACITANCE

Parameter Symbol	Parameter Description	Test Setup	Тур.	Max.	Unit
CIN	Input Capacitance	VIN = 0	7.5	9.5	pF
Соит	Output Capacitance	Vout = 0	8	10	pFC
CIN2	Control Pin Capacitance	V _{IN} = 0	10	13	pF

■ FBGA PIN CAPACITANCE

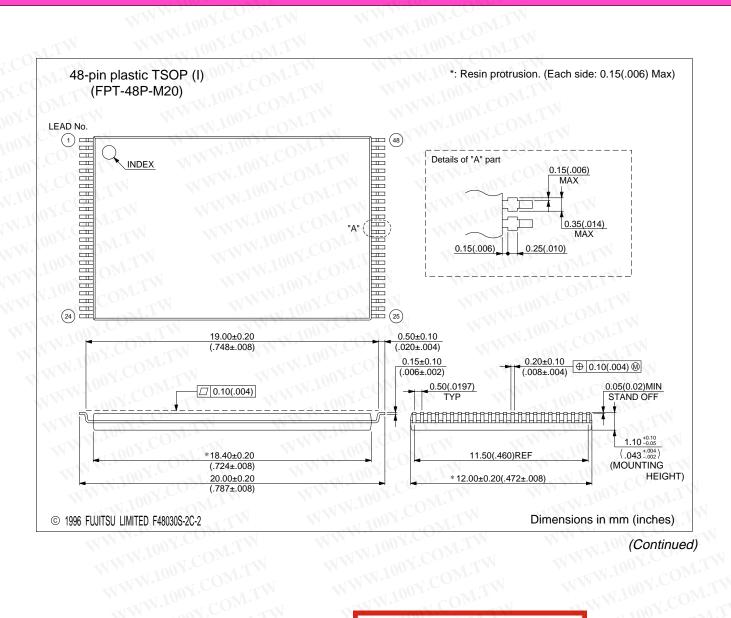
Parameter Symbol	Parameter Description	Test Setup	Тур.	Max.	Unit
CIN	Input Capacitance	V _{IN} = 0	7.5	9.5	pF
Соит	Output Capacitance	Vout = 0	8	10	pF
CIN2	Control Pin Capacitance	V _{IN} = 0	10	13	pF

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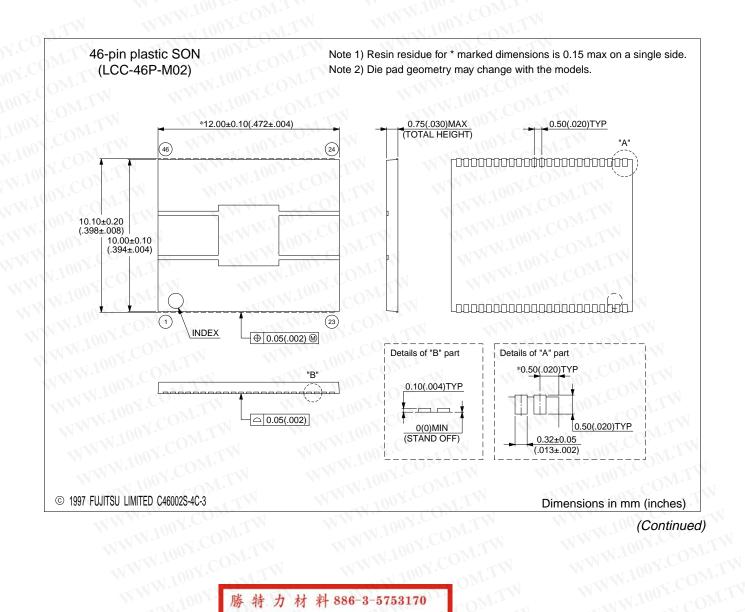
WWW.100Y L100Y.COM PACKAGE DIMENSIONS 48-pin plastic TSOP (I) *: Resin protruction. (Each side: 0.15(.006) Max) (FPT-48P-M19) LEAD No. WWW.100Y.COM. (1)WWW.100Y.COM.TW Details of "A" part INDEX 0.15(.006) WWW.100Y.COM.TW MAX 0.35(.014) 1 "A" <u>с п</u> MAX 0.15(.006) 0.25(.010) HHH п HHHH WWW.100Y.CON (24) (25) 20.00±0.20 *12.00±0.20 (.787±.008) (.472±.008) *18.40±0.20 11.50REF 1.10 +0.10 $(.724 \pm .008)$ (.460)(.043^{+.004}) (MOUNTING HEIGHT) 0.50(.0197) 0.05(0.02)MIN 0.10(.004) STAND OFF TYP 0.15±0.05 0.20±0.10 (.008±.004) ⊕ 0.10(.004) ₪ $(.006 \pm .002)$ 0.50±0.10 19 00+0 20 $(.020 \pm .004)$ $(.748 \pm .008)$ © 1996 FUJITSU LIMITED F48029S-2C-2 Dimensions in mm (inches) WWW.100Y.COM.TW WWW.100<u>7</u>. WWW.100Y WWW.100Y.COM.

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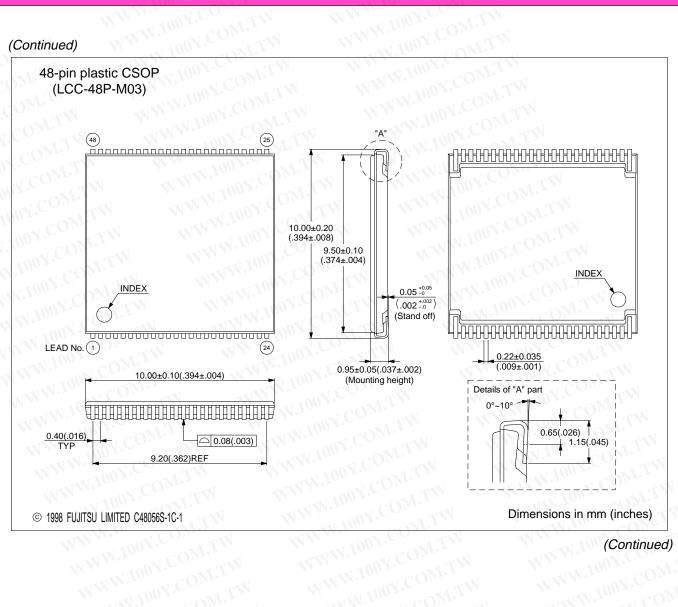
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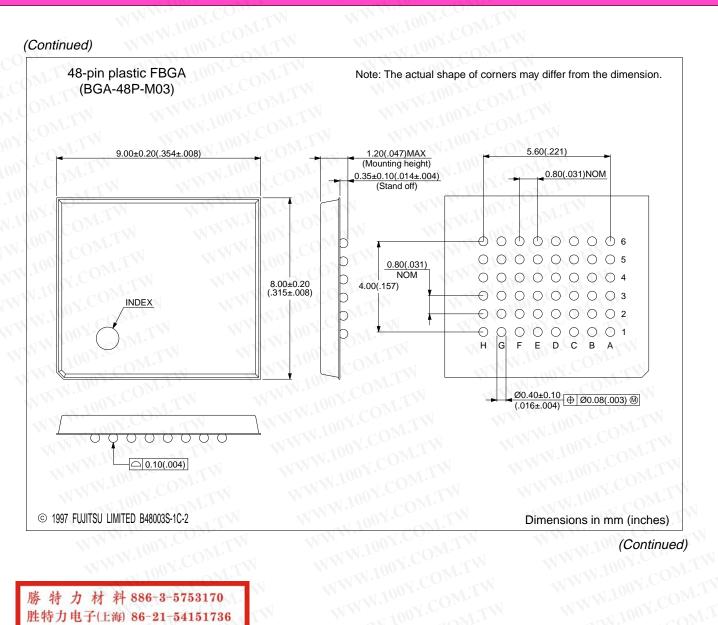
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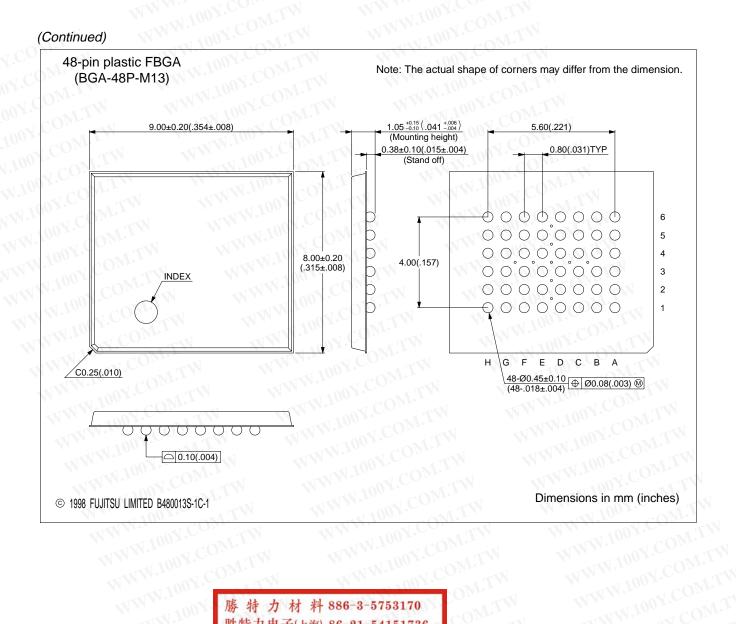
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